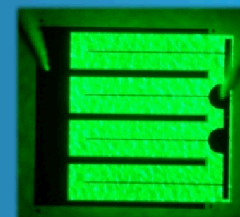
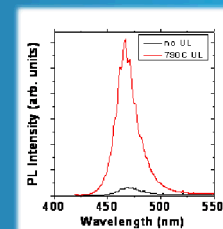
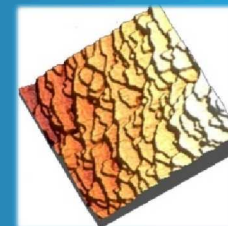


**SSLS
EFRC**

SOLID-STATE LIGHTING SCIENCE
ENERGY FRONTIER RESEARCH CENTER

Group III-Nitride Growth for Solid State Lighting

Daniel D. Koleske, J. Randall Creighton,
Michael E. Coltrin, Mary H. Crawford,
Stephen R. Lee, and Andrew Armstrong



Work supported by the US Department of Energy, Office of Basic Energy Sciences



Sandia National Laboratories, a multiprogram laboratory managed and operated by Sandia Corporation, a wholly owned subsidiary of Lockheed Martin Corporation, for the U.S. Department of Energy's National Nuclear Security Administration under contract DE-AC04-94AL85000.



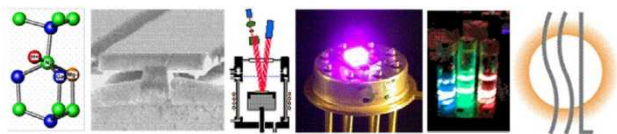


Topics for Discussion

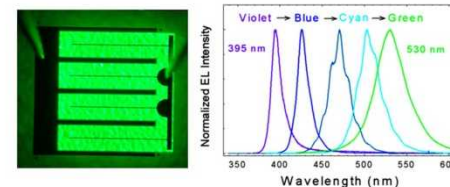
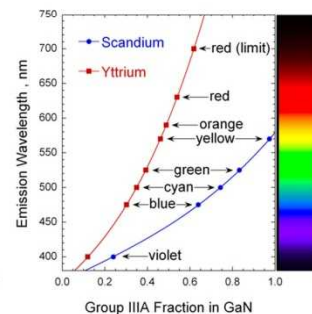
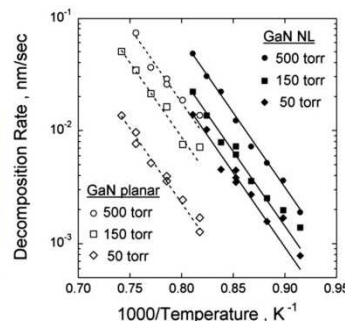
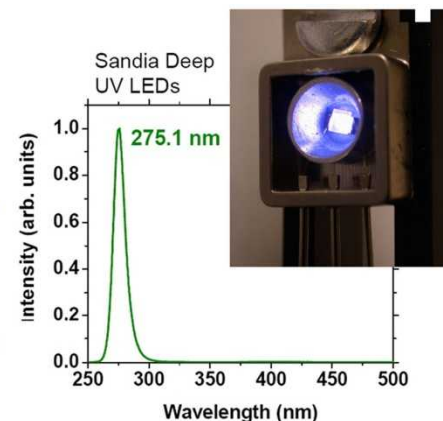
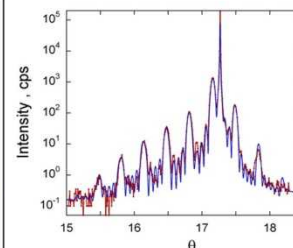
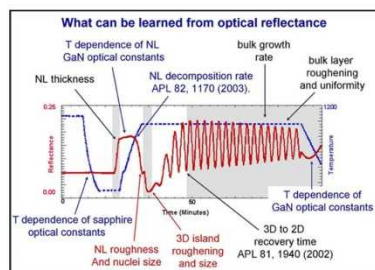
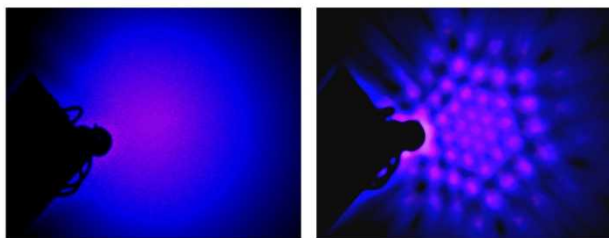
- Current SSL programs at Sandia
- Heteroepitaxy studies – GaN on sapphire
- MOCVD reactor chemistry
- InGaN growth related to improving LED brightness
- Semipolar GaN growth – brighter green?

Long Legacy of R & D in SSL and Group III - Nitrides

Final Report on Grand Challenge LDRD Project:



A Revolution in Lighting – Building the Science and Technology Base for Ultra-Efficient Solid-State Lighting



- Sandia has been involved in group III nitride research since 1997.
- Sandia was there from the start. In 1999, Jeff Tsao, Jeff Nelson, Roland Haitz (HP) and Fred Kish (HP) wrote a “white paper” to DOE for increased support for LED development for SSL.
- Sandia has been supported both internally (LDRD) and externally (BES, NETL, and DARPA) for many years. From 2001 to 2004 it was supported by a 8 M\$ grand challenge LDRD at Sandia. More recently, support has been provided by DOE basic energy sciences (BES), and additional LDRDs, and EERE/NETL.

Current SSL related programs at Sandia

- **SSL Science (SSLS) Energy Frontier Research Center (EFRC) – (DOE/BES) - 2010 - 2015**
- Semi-polar GaN Materials Technology for High IQE Green LEDs – (EERE/NETL) – 1/15/2010 to 1/15/2013.
- Driving Down HB-LED Costs: Implementation of Process Simulation Tools and Temperature Control Methods for High Yield MOCVD - with Veeco - (EERE/NETL) - 5/1/2010 - 4/30/2012
- Novel Defect Spectroscopy of InGaN Materials for Improved Green LEDs (EERE/NETL) 04/01/08 - 03/31/11 – just finished.
- Ten previous EERE/NETL funded programs and internal LDRD programs on SSL, including Grand Challenge LDRD (2001-2004).



We are one of 46 Department of Energy Office of Science EFRCs



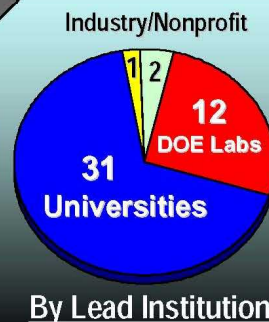
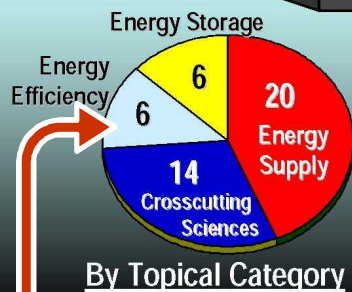
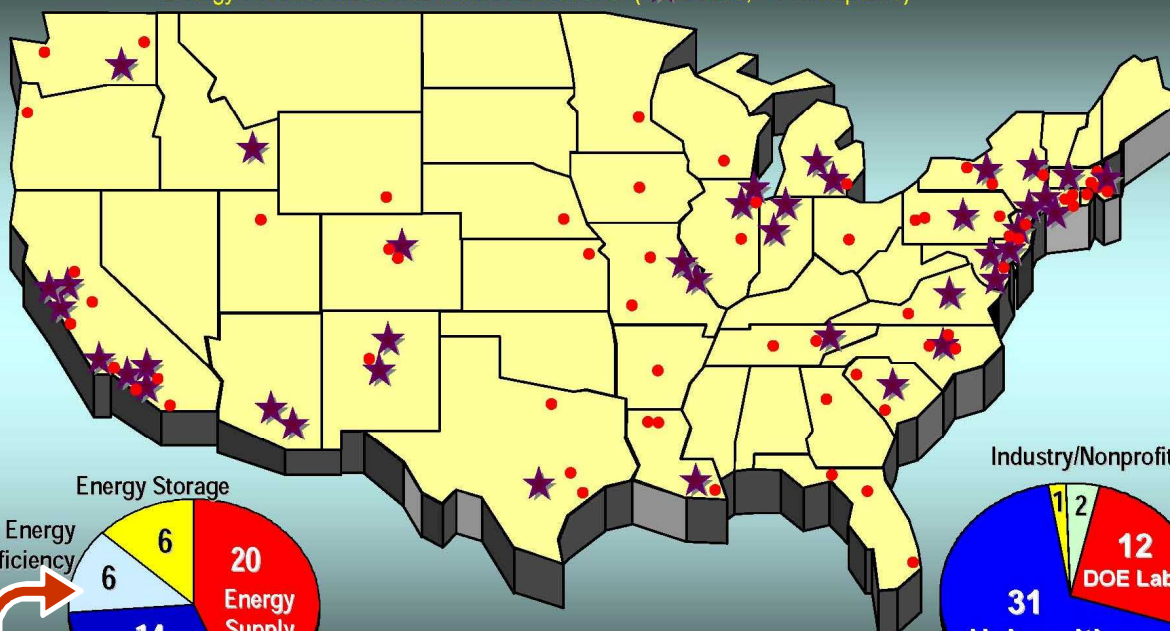
U.S. DEPARTMENT OF
ENERGY

Office of
Science

Energy Frontier Research Centers Tackling Our Energy Challenges in a New Era of Science

46 centers awarded, representing 103 participating institutions in 36 states plus D.C.

Energy Frontier Research Center Locations (★ Leads; ● Participants)



- Goal: To establish the scientific foundation for a fundamentally new U.S. energy economy
- Overall Budget: \$777M over 5 years beginning Aug 2009
- Our Budget: \$18M over 5 years

We are one of 6 EFRCs focused on efficiency, and the only one focused on SSL

People & Resources:

2011 Snapshot (33+20)

Management Team

Jerry Simmons

Mike Coltrin

Jeff Tsao

Thrust Leaders

Mary Crawford

Art Fischer

George Wang

Senior Staff

Andy Armstrong

Bob Biefeld

Igal Brener

Weng Chow

Jianyu Huang

Dan Koleske

Francois Leonard

Qiming Li

Willie Luk

Jim Martin

Normand Modine

May Nyman

Lauren Rohwer

Eric Shaner

Ganesh Subramania

Jon Wierer

Post-Docs & Students

Tania Henry

Emil Kadlec

Jeremy Wright

Business & Administrative

Rene Sells

Alyssa Christy

Chris Monroe

Katelynn Florentino

Technical Support

Jeff Figiel

Tony Coley

Kris Fulmer

Karl Westlake

Integrated Materials Research Lab



Center for Integrated Nanotechnologies



Microsystems Engineering Sciences & Applications Complex



THE UNIVERSITY of
NEW MEXICO



Los Alamos
NATIONAL LABORATORY



University of New Mexico

Professor Steve Brueck

Sasha Neumann

Yale University

Professor Jung Han

Chris Yerino

Ben Leung

Northwestern University

Professor Lincoln Lauhon

Sonal Padalkar (PD)

Jim Riley

Los Alamos National Lab

Rohit Prasankumar

Prashanth Upadhy

Rohan Kekatpure (PD)

Minah Seo (PD)

Rensselaer Polytechnic Univ

Professor Fred Schubert

Di Zhu

Ahmed Noemaun

Qi Dai

University of Massachusetts

Professor Dan Wasserman

Troy Ribaud

UC Merced

Professor David Kelley

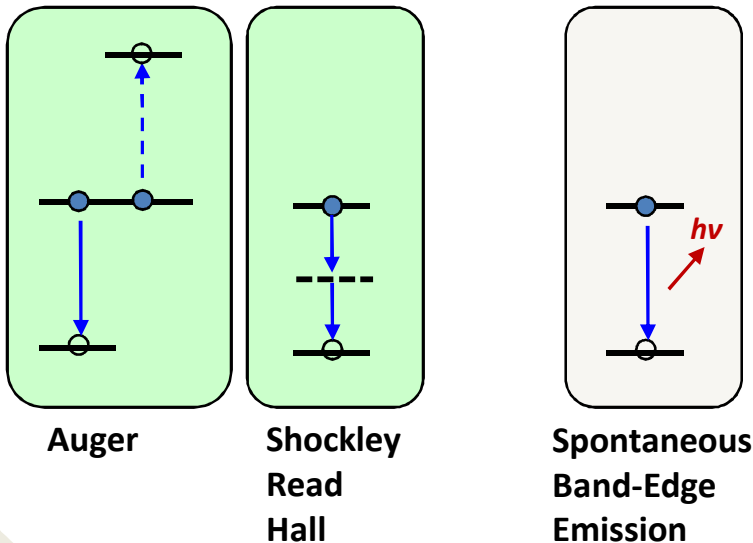
Philips Lumileds

Mike Craven

Our EFRC's Scientific Thrusts

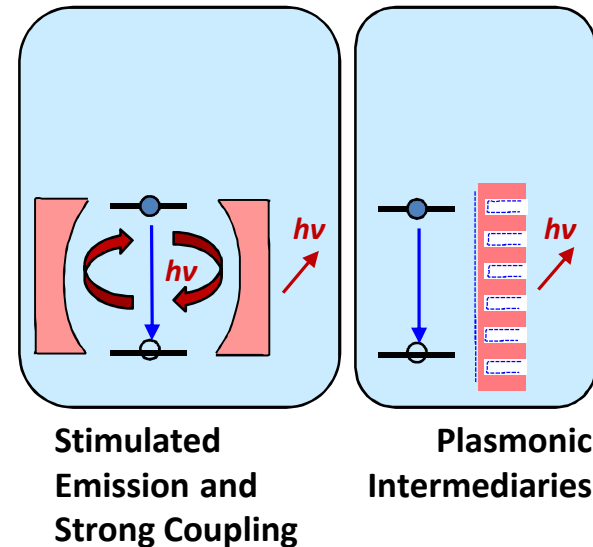
1 Competing Radiative and Non-Radiative Processes

Develop a microscopic understanding of the competition between radiative and non-radiative e-h recombination: spontaneous emission from planar structures.



2 Beyond Free-Space Spontaneous Emission

Explore energy conversion routes that short-circuit conventional spontaneous emission but end in free-space photons.



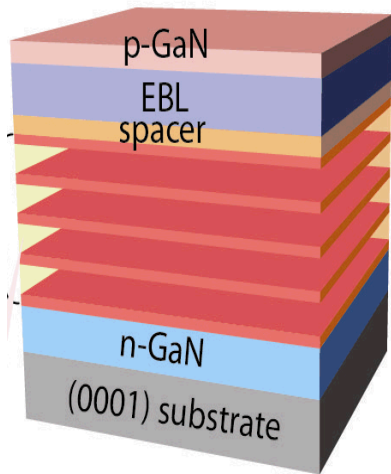
3 Beyond-2D

Explore the use of non-planar nanoscale structures to modify energy conversion routes so that they may be (a) isolated and better understood, and (b) engineered and optimized.

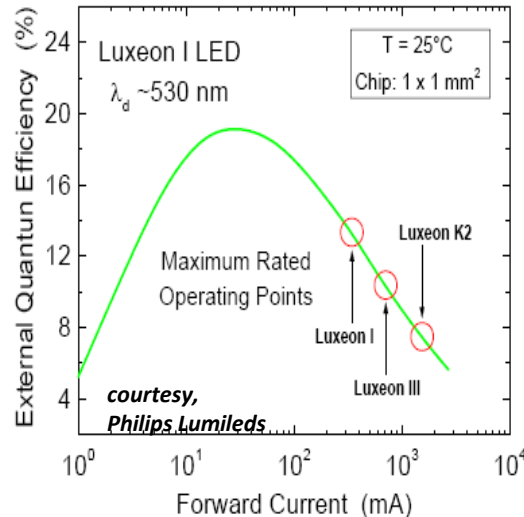
Mary Crawford (PI)
Weng Chow,
Dan Koleske,
Andy Armstrong,
Normand Modine,
Fred Schubert (RPI)

1.1 Origin of Efficiency Droop: Beyond the A,B,C Approximation

Typical Device Heterostructure



Macroscopic observable



Usual A,B,C Approximation

$$\varepsilon = \underbrace{\left(\frac{V_{ph}}{V_{ph} + IR} \right)}_{\substack{\text{Joule efficiency} \\ \text{(resistive losses)}}} \cdot \underbrace{\varepsilon_{inj}}_{\substack{\text{Injection efficiency} \\ \text{(carrier overshoot/escape)}}} \cdot \underbrace{\frac{BN^2}{AN + BN^2 + CN^3 + \dots}}_{\substack{\text{Shockley-Read-Hall (defect-mediated)} \\ \text{Spontaneous Emission}}} \cdot \underbrace{\varepsilon_{ext}}_{\substack{\text{Extraction efficiency} \\ \text{(photon trapping and absorption)}}}$$

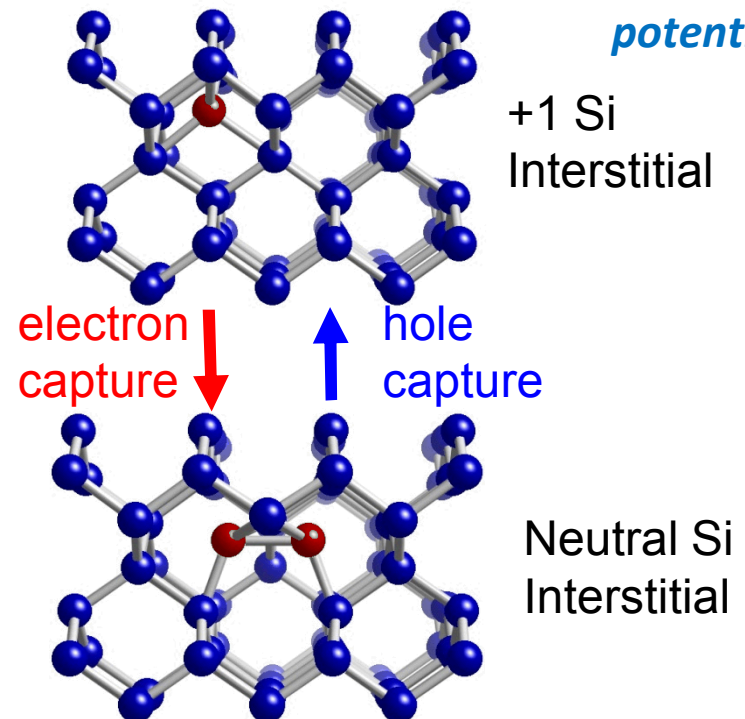
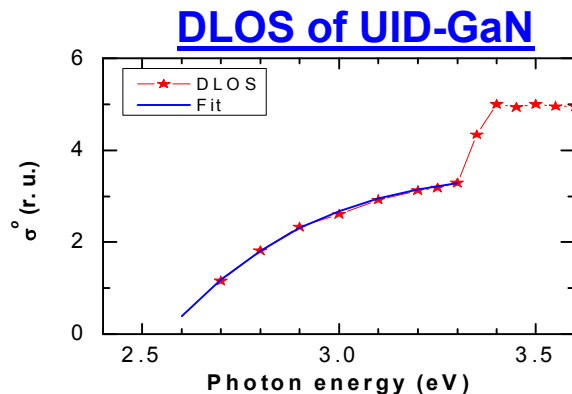
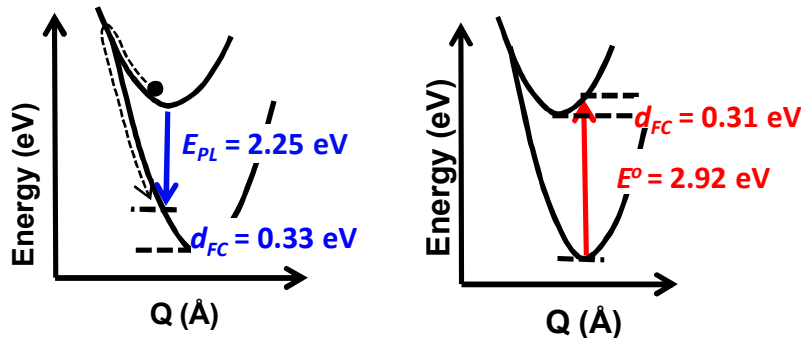
ε_{joule} (Joule efficiency) is associated with V_{ph} and IR .
 $2.8V$ and 0.6Ω are associated with V_{ph} and IR respectively.
 ε_{IQE} (Internal quantum efficiency) is associated with the BN^2 term.
 CN^3 is associated with Auger-like processes.
 ε_{ext} is the extraction efficiency.

1.2 Deeper into Point Defects: Fundamental Properties of V_{Ga}

Deep Level Optical Spectroscopy:
Measure deep-level densities, cross-sections, Franck-Condon shifts

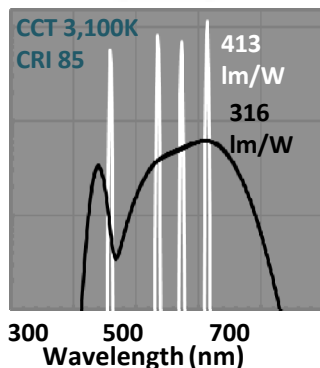
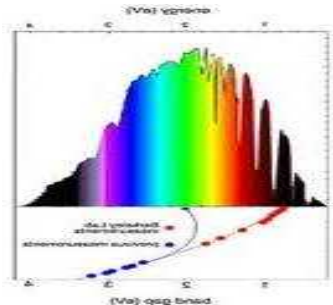
Andy Armstrong (PI)
Normand Modine
Dan Koleske
Mary Crawford

Density Functional Theory:
Ab initio calculations of E_0 ,
 $\hbar\omega$, S using realistic multi-dimensional anharmonic potentials

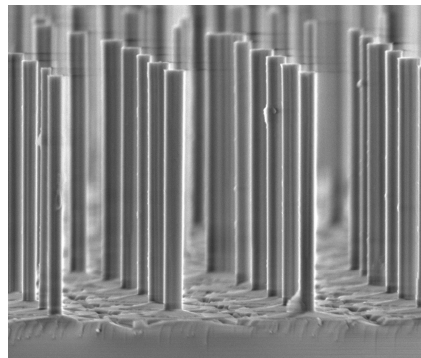


3.1 Beyond 2D: 1D Nanowire Synthesis, Properties, Architectures

High InGaN compositions needed to span the desired SSL wavelengths

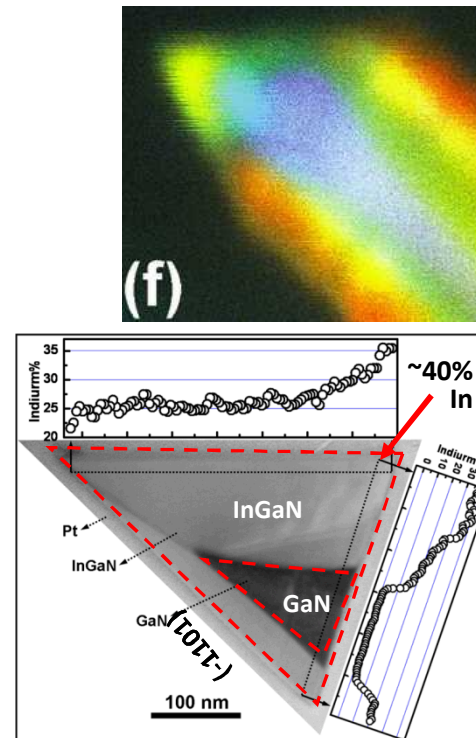


High aspect ratio enables strain accomodation

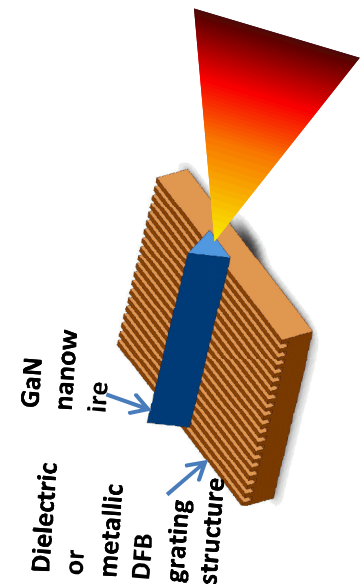


George Wang (PI)
Qiming Li,
Jianyu Huang
Igal Brener,
Francois Leonard
Rohit Prasankumar
Lincoln Lauhon

Measurements verify 40% InGaN, with anisotropies



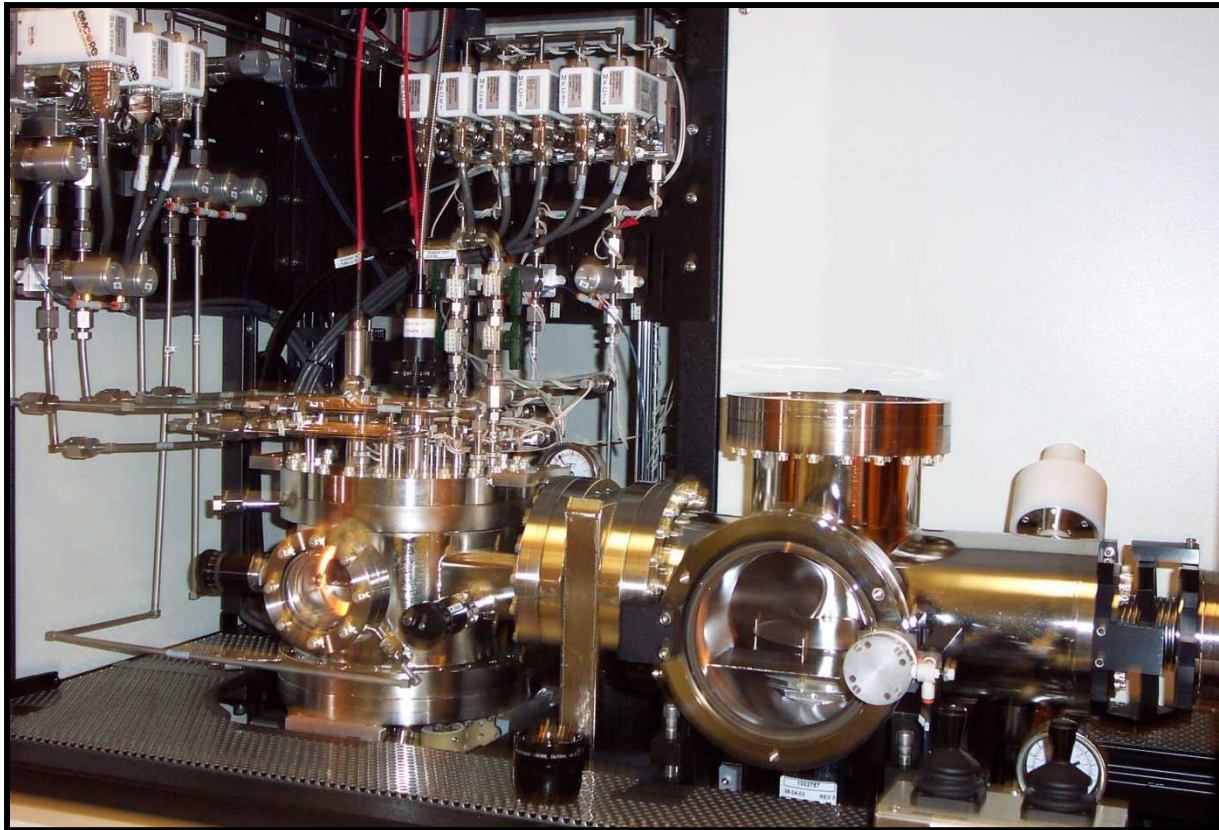
Future work: InGaN nanowire lasing!



Topics for Discussion

- Current SSL programs at Sandia
- Heteroepitaxy studies – GaN on ...
- MOCVD reactor chemistry
- InGaN growth related to improving LED brightness
- Semipolar GaN growth – brighter green?

Three D-125 Veeco short-jar MOCVD systems at Sandia



- **MOCVD reactor** – Veeco D125 short-jar - 3-2" wafers simultaneously.
- **Precursors** – trimethyl sources of In, Al, and Ga, and Mecp_2Mg and SiH_4 for p- and n-type doping.
- **Gases** – NH_3 , N_2 , H_2 (no H_2 for InGaN)
- **Temperature** – GaN at 1050°C , InGaN at $680 - 880^\circ\text{C}$.

**Growth differences between InGaN and GaN are:
lower temperature, higher NH_3 , no H_2 , slower growth rate (less total MO).**



Typical “two step” heteroepitaxy of GaN on sapphire

- 1) Sapphire heated to high temperature (1050 – 1100 °C) in H_2 to “clean” the surface; surface sometimes exposed to NH_3 at high temperature.
- 2) Grow 20 – 30 Å GaN NL at 500 – 600 °C; as grown NL contains “cubic” material with stacking faults.
- 3) Heat GaN NL to 1000 – 1080 °C in flowing H_2 , N_2 , and NH_3 . Wurtzite GaN nuclei form.

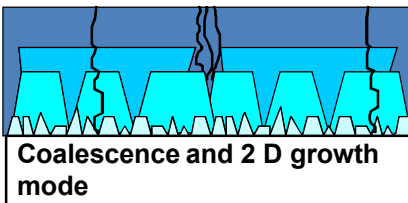
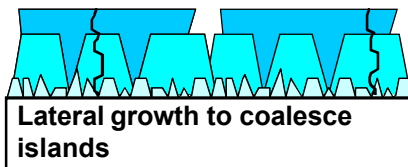
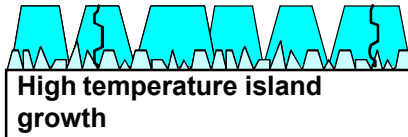
Sapphire high temperature
cleaning and nitriding

Low temperature GaN
nucleation layer

Ramp & anneal

Step 1

Step 2

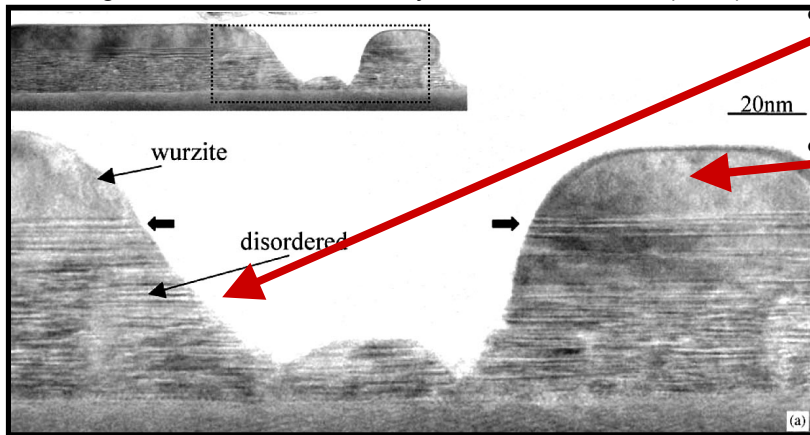


- 4) At high temperature, Ga source is turned on. Isolated GaN grains grow on the GaN nuclei from the decomposition of the GaN NL. Some dislocations propagate up from the GaN grains.
- 5) Islands grow laterally / vertically; grains begin to coalesce. Growth conditions can be tuned to increase / decrease lateral growth rate.
- 6) When grains have coalesced, growth becomes 2-D. Dislocations are formed as GaN grains coalesce to accommodate grain twist / tilt.

Based on work from K. Hiramatsu, et al., *Journal of Crystal Growth* 115, 628 (1991).

GaN morphology evolution on sapphire

Figure from Lada et al., J. Crystal Growth 258, 89 (2003).

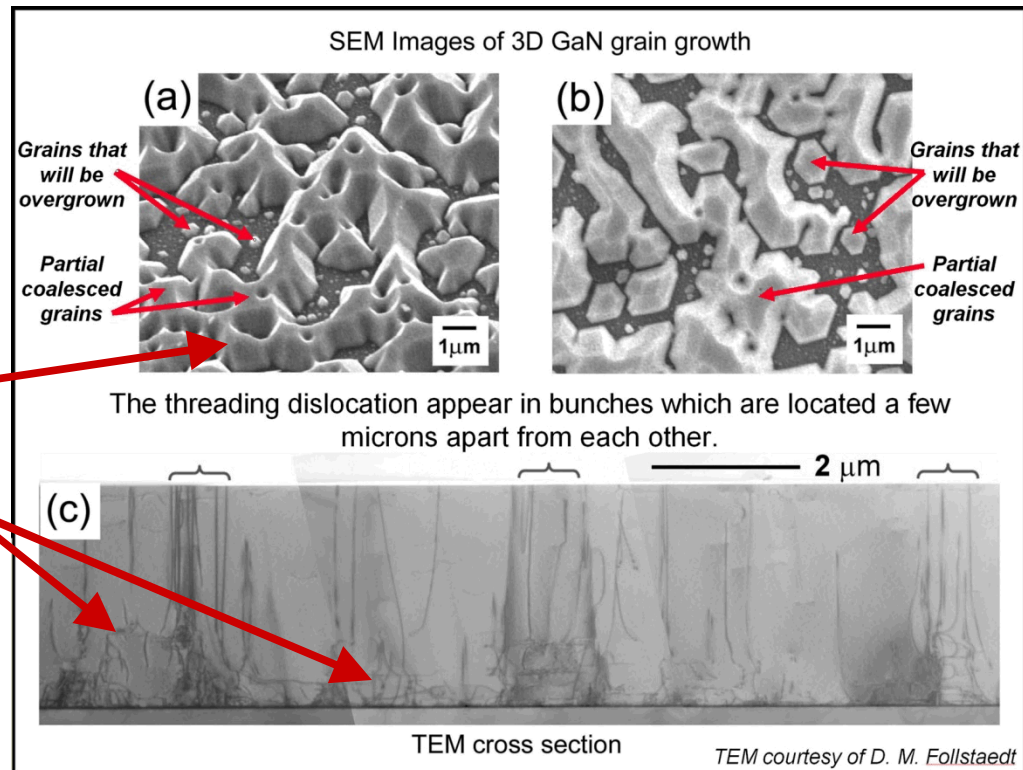


As grown GaN nucleation layers contain disordered GaN with many stacking faults.

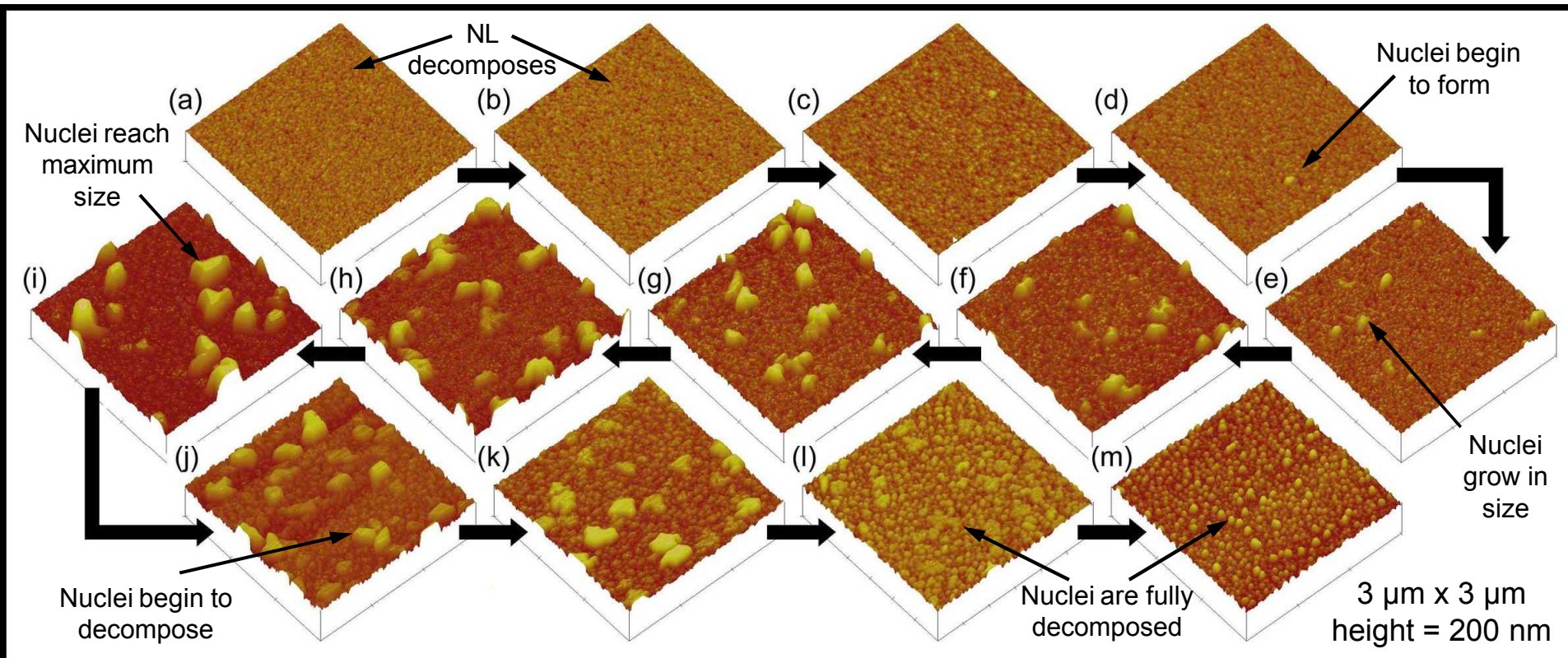
Once annealed, wurtzite GaN forms on top of GaN NL, forming nano-sized GaN nuclei from which further high temperature GaN growth occurs.

- High temperature growth on the GaN nuclei produces GaN grains.
- Growth conditions can be varied to enhance the pyramidal growth mode delaying coalescence. Dislocations are bent laterally on pyramidal facets
- Dislocations are concentrated in bunches located microns apart.

Works! But not Ideal!



Mechanism for GaN nuclei formation as the nucleation layer is annealed.



Arrows indicate increasing annealing temperature + time in H_2 , N_2 , and NH_3 . *Koleske et al., J. Crystal Growth 273, 86 (2004).*

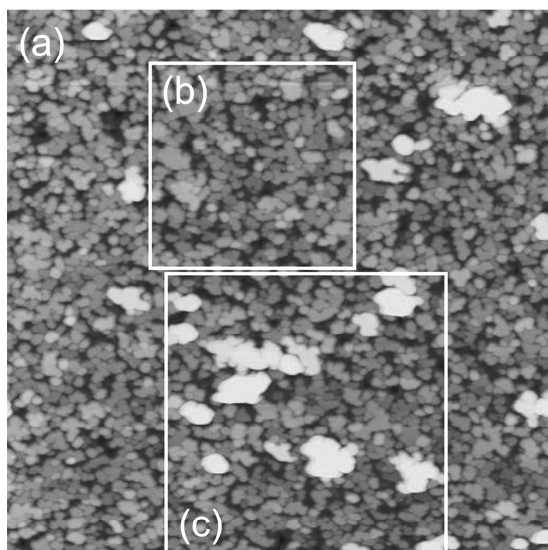
Mechanism for GaN nuclei formation → NL decomposes during annealing, Ga atoms desorb into the gas phase and reincorporate with NH_3 to form GaN nuclei.

Key mechanism: Gas phase desorption and reincorporation not surface diffusion.

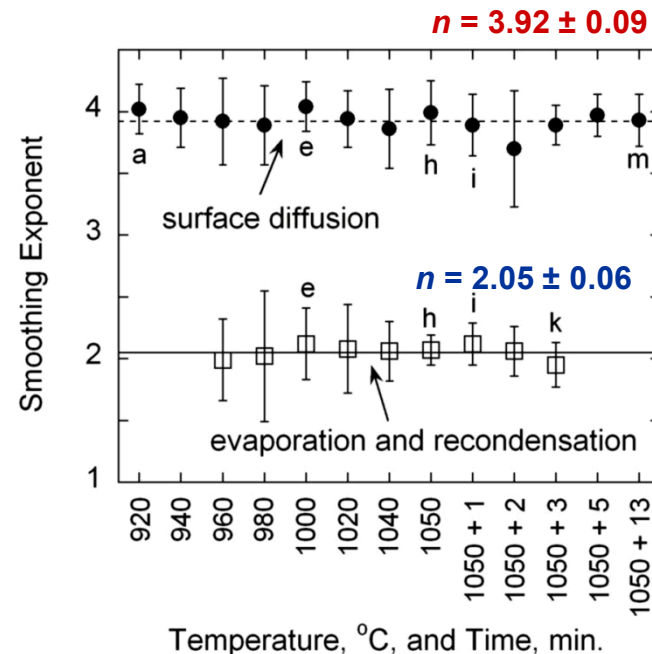
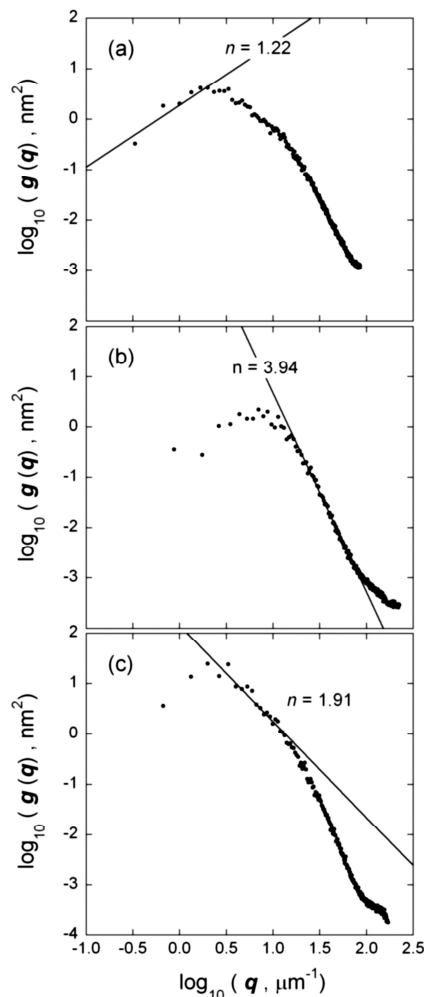
PSD analysis of GaN nucleation layer evolution

AFM scan of NL at 1000 °C

Low temperature deposited GaN NL is smoothed via surface diffusion, $n = 4$.



GaN nuclei form out of deposited GaN NL via evaporation and recondensation mechanism, $n = 2$.



Consistent with gas phase transport model of Mitchell, *et al.*, J. Crystal Growth 222, 144 (2001).

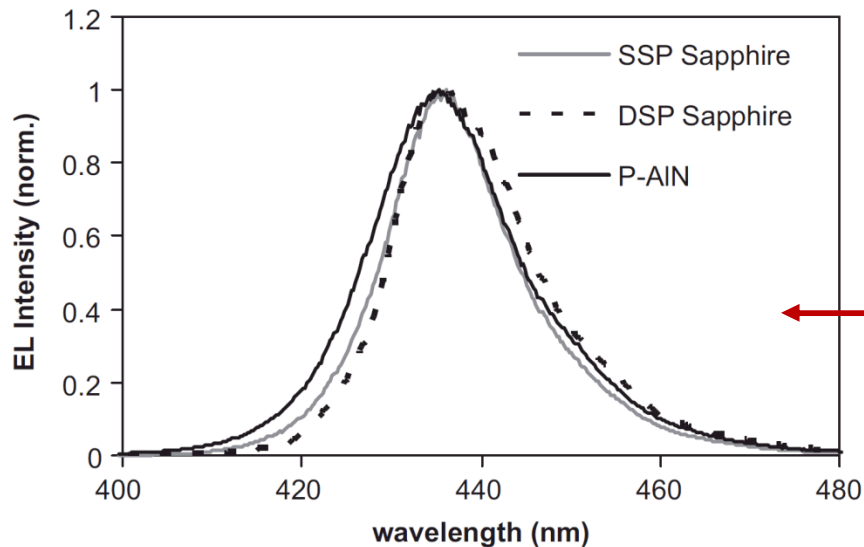
Koleske *et al.*, J. Crystal Growth 273, 86 (2004).

LED growth on wafer-bonded sapphire-on-polycrystalline AlN substrate

Worked with Aonex Technologies Inc. to develop LED structures on wafer bonded sapphire to polycrystalline AlN substrates.

Coefficient of Thermal Expansion matched.

We conclude that the 2-step growth process on the composite substrates proceeds in a similar way to growth on sapphire – similar dislocation density.



T. Pinnington, et al., J. Crystal Growth 310, 2514 (2008).

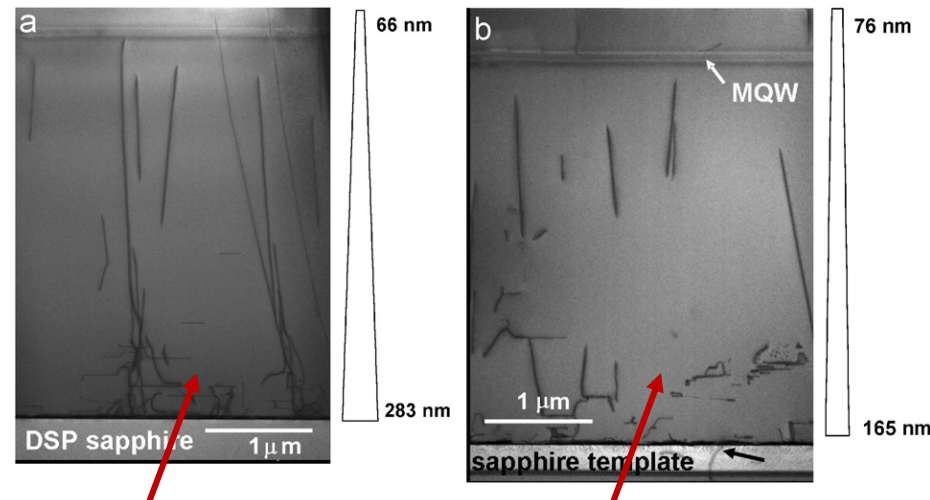


Fig 5. (a) DSP sapphire and (b) sapphire/P-AlN composite substrate. Foil thickness as determined by SEM is shown at the right of each image.

Fig. 6. Normalized electroluminescence spectra of LED structures grown on a composite sapphire/P-AlN substrate and bulk sapphire substrates show similar wavelengths near 440 nm.

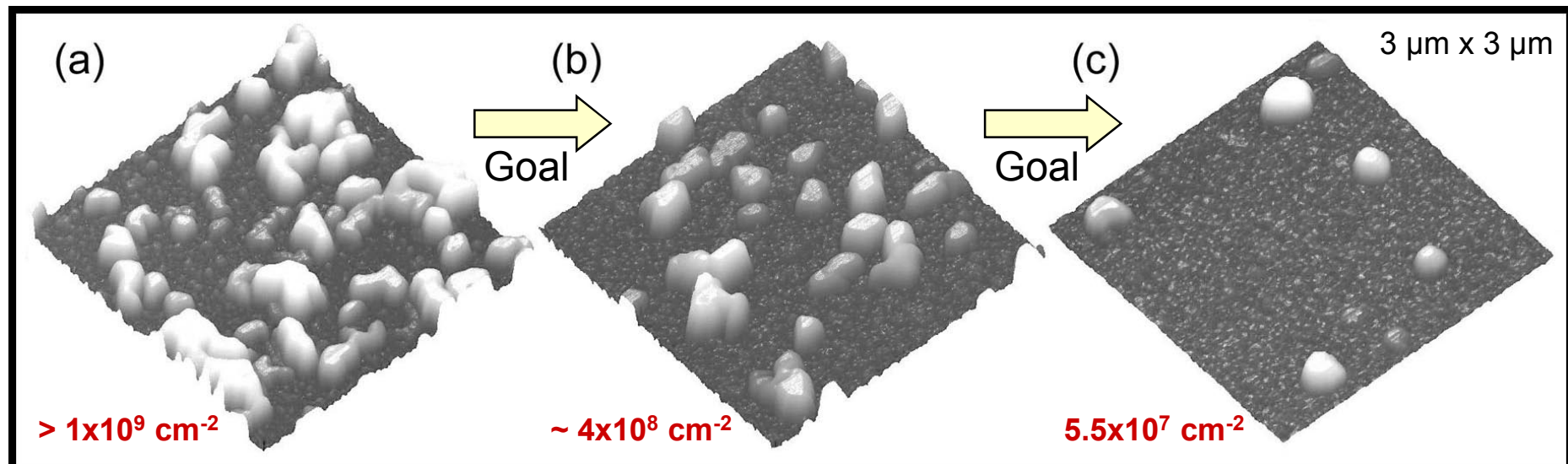
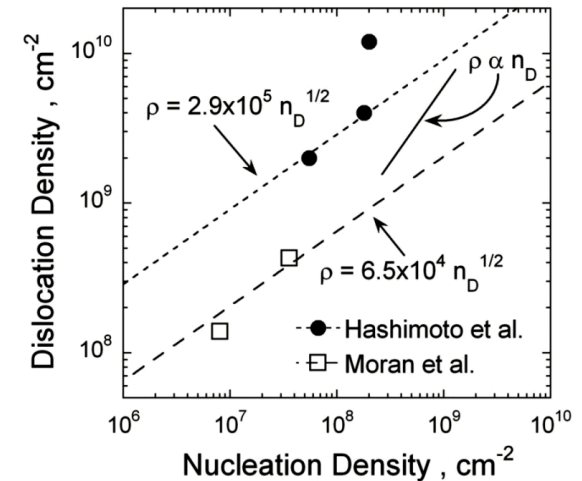
Later confirmed GaN growth on GaN wafer bonded to poly-AlN – maintained low dislocation density $\sim 10^6 \text{ cm}^{-2}$.

EERE/NETL program on GaN dislocation reduction on sapphire (2007 - 18 month)

- If dislocations form to accommodate grain twist and tilt, then the GaN nuclei density, n_D , should correlate with the dislocation density, ρ .

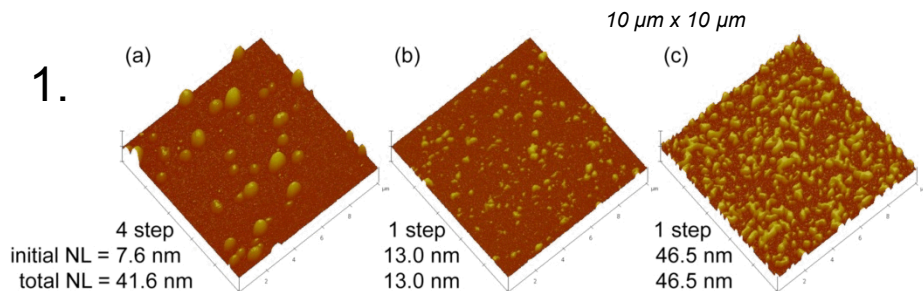
$$\rho = \text{const} \times n_D^{1/2} \quad \longrightarrow$$

- Goal is to reduce the dislocation density of GaN films on sapphire from $5 \times 10^8 \text{ cm}^{-2}$ to $1 \times 10^8 \text{ cm}^{-2}$ by limiting the nuclei density while maintaining high lateral growth rate.

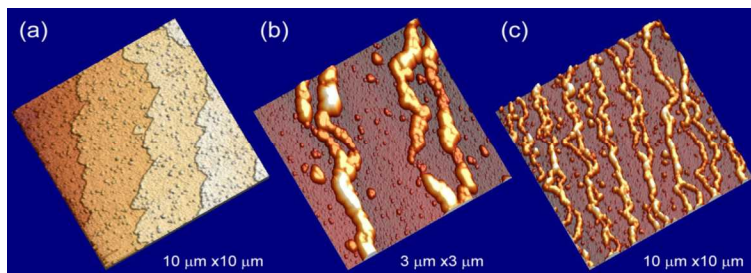


Steps taken to reduce dislocation density

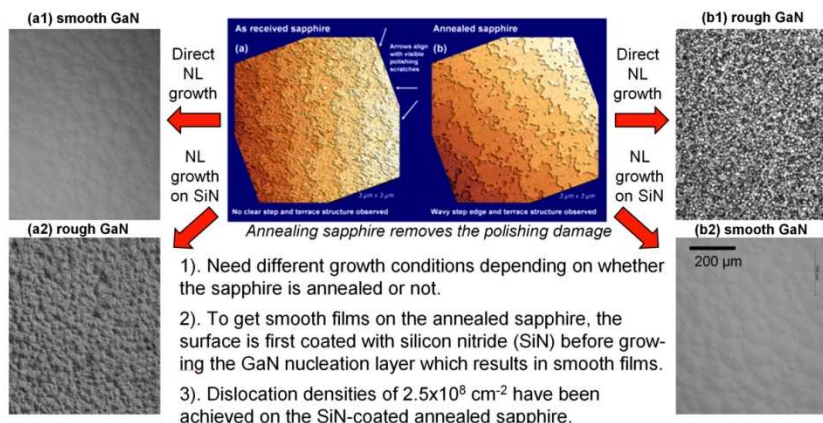
1.



2.



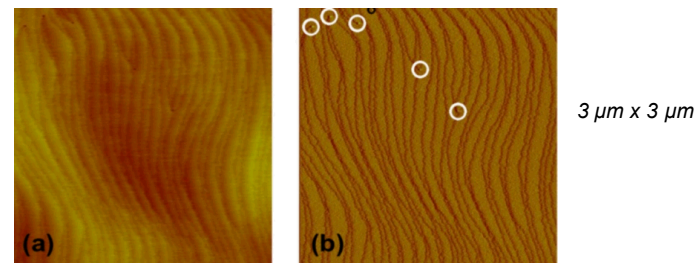
3.



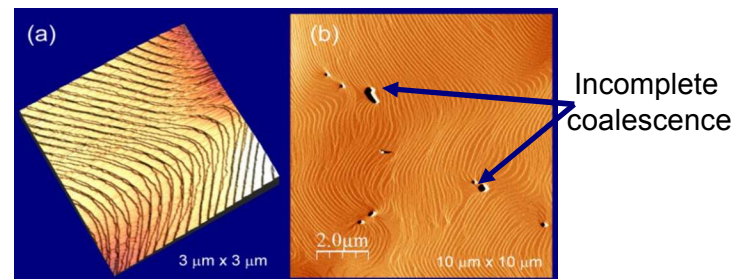
Using the current process dislocation densities of $\sim 2.5 \times 10^8 \text{ cm}^{-2}$ were achieved.

1. Reduce initial NL thickness – can use multiple NL growth and annealing sequences to build up GaN grains.
2. Anneal sapphire wafers – nucleation enhanced along the step edges.
3. Silicon nitride was necessary on annealed sapphire wafers.
4. AFM used to count dislocations – achieved total dislocation densities $< 1 \times 10^8 \text{ cm}^{-2}$.
5. Some issues with incomplete coalescence.

4.



5.



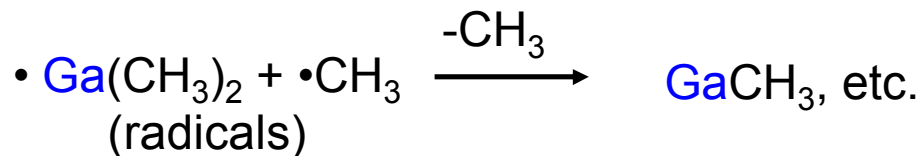


Topics for Discussion

- Current SSL programs at Sandia
- Heteroepitaxy studies – GaN on ...
- **MOCVD reactor chemistry**
- InGaN growth related to improving LED brightness
- Semipolar GaN growth – brighter green?

Particle nucleation

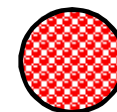
Ga pathway – via pyrolysis, higher activation energy, exhibits H_2 dependence



radical
recombination
reactions

“Nucleus”
(10-100 atoms)

CVD

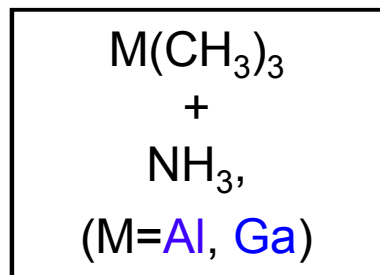


nanoparticle
(10^4 - 10^7 atoms)

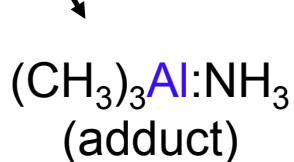
most mass loss
may occur during
this step,
strong residence
time dependence,
up to τ^3

AlGa_{0.5}N model see
Coltrin JCG 2006

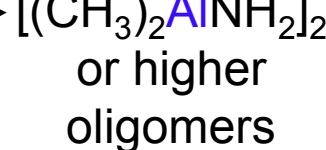
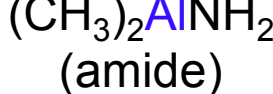
Al pathway – concerted, lower activation energy, no carrier gas dependence



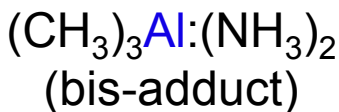
$\pm \text{NH}_3$



$-\text{CH}_4$



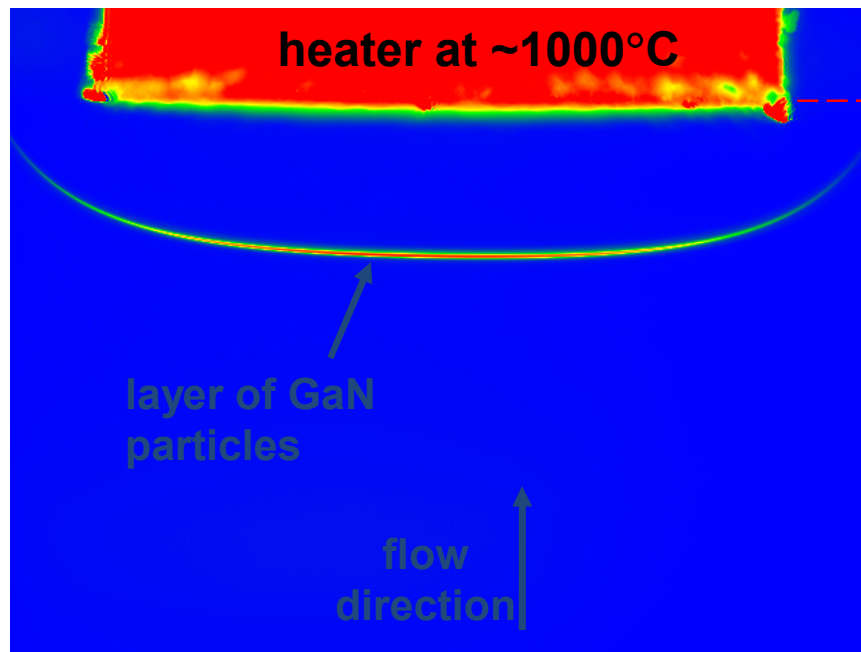
$-\text{nCH}_4$



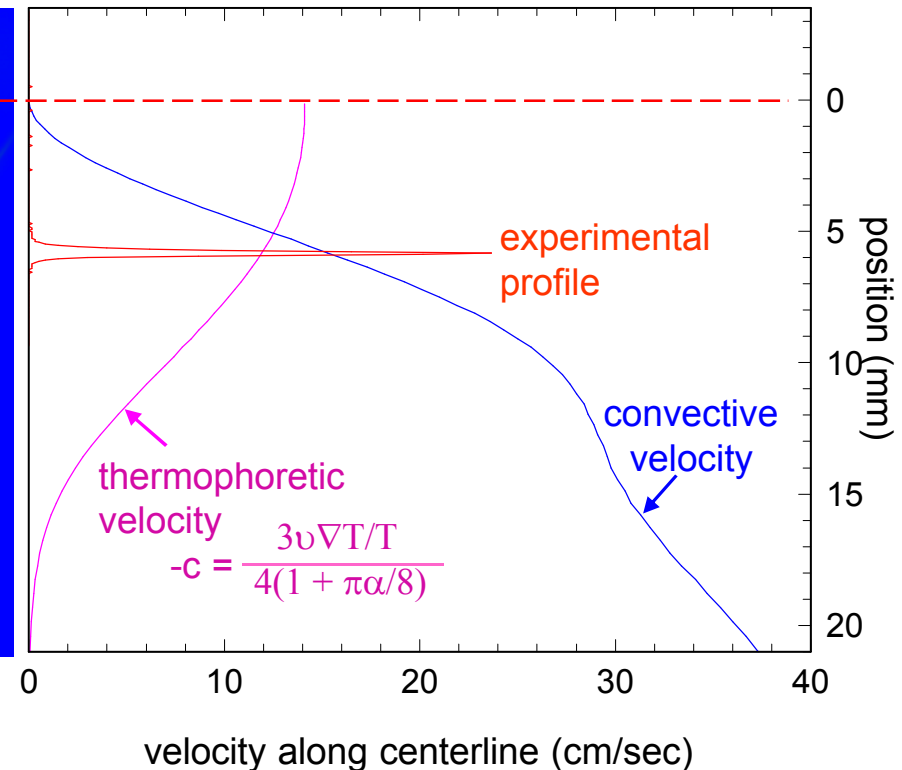
In situ laser light scattering reveals nanoparticles during GaN, AlN, and InN MOCVD

Inverted stagnation point
flow (SPF) reactor

The calculated particle position
(**thermophoretic force** = -**viscous force**)
agrees well with experiment



Nanoparticles are well within the thermal
boundary layer, residing at temperatures of
600-700°C



AlN particles are 35-50 nm in diameter (APL 2002)

Summary/Significance of III-N chemistry studies

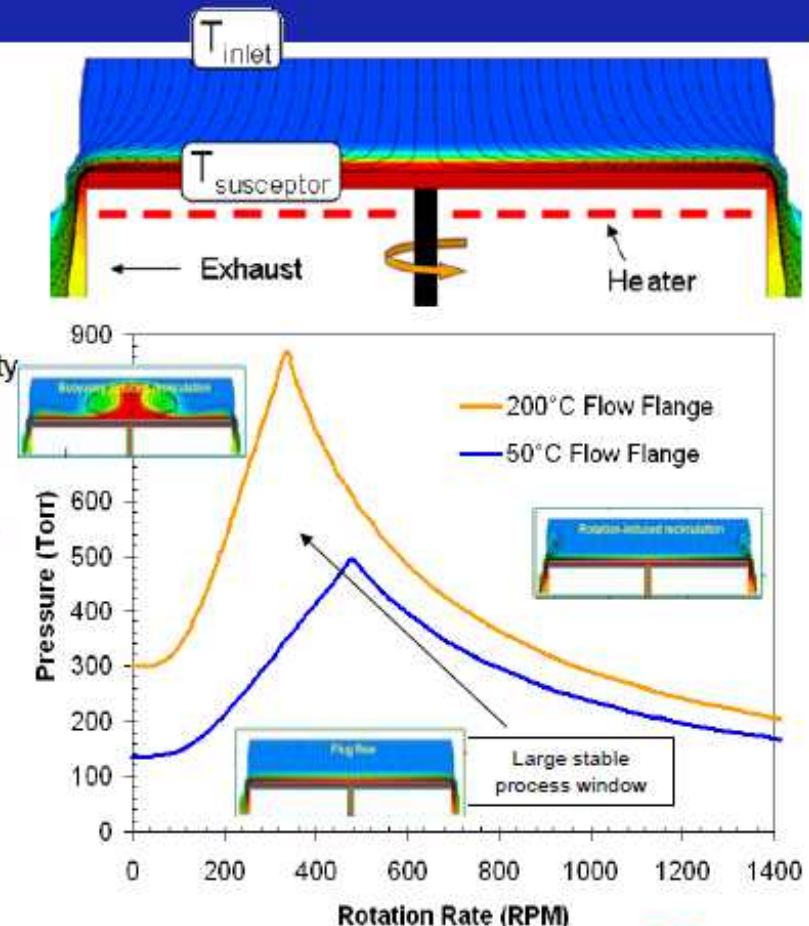
- Nucleation and growth of **nanoparticles** is the fundamental mechanism for loss of group-III flux during GaN, AlN, and AlGaN MOCVD
- Most parasitic chemistry requires high temperatures, occurs in the boundary layer
- Our MOCVD model with a particle nucleation and growth mechanism (via approximations) reproduces most experimental observations for GaN/AlGaN (Coltrin JCG2006)

(mostly for flow stability reasons) Veeco has developed a heated flow flange ($T_{\text{inlet}} \sim 200^{\circ}\text{C}$) for their K465i system

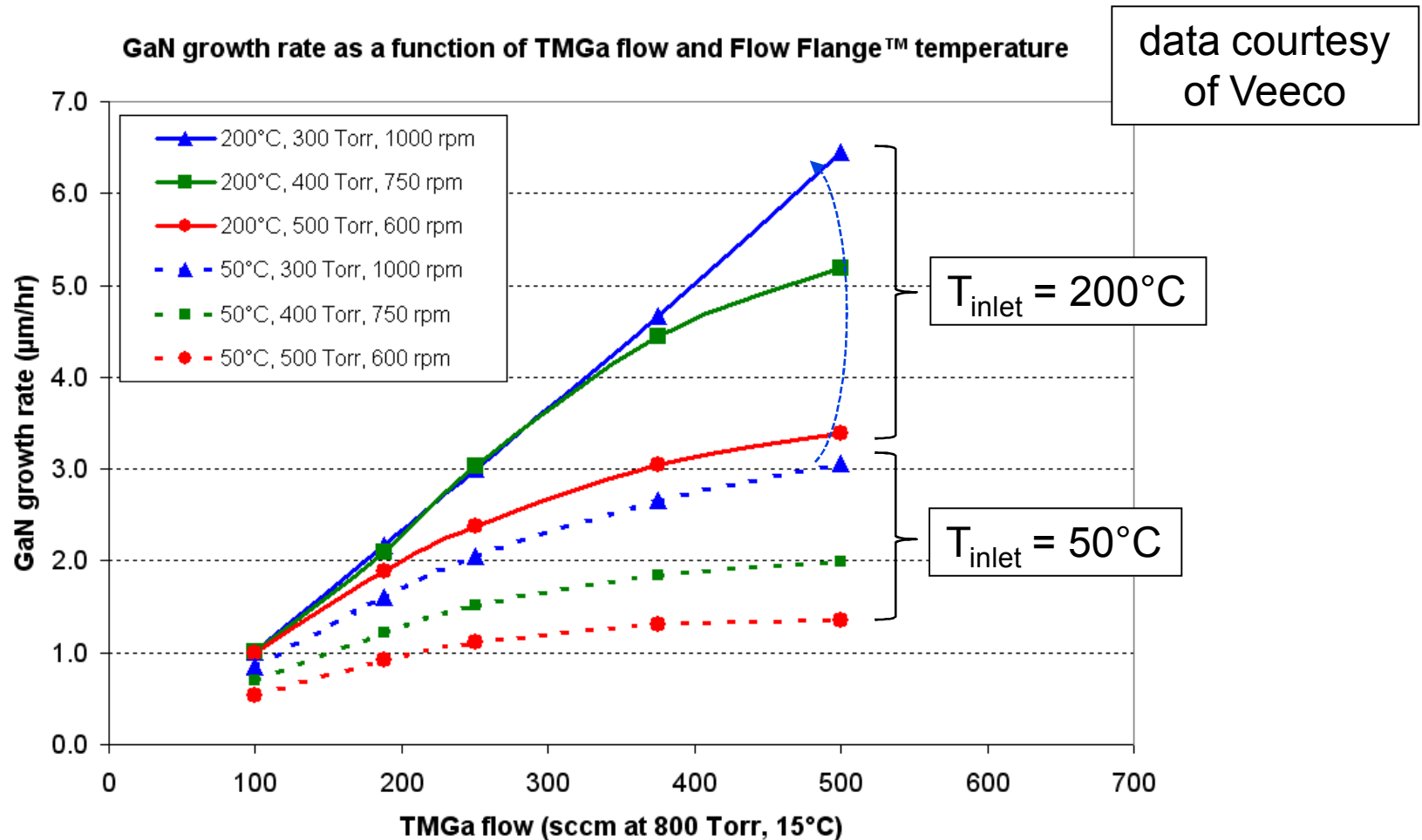
10.0 Heated Flow Flange – Benefits

Greater gas inlet temperature (T_{inlet}):

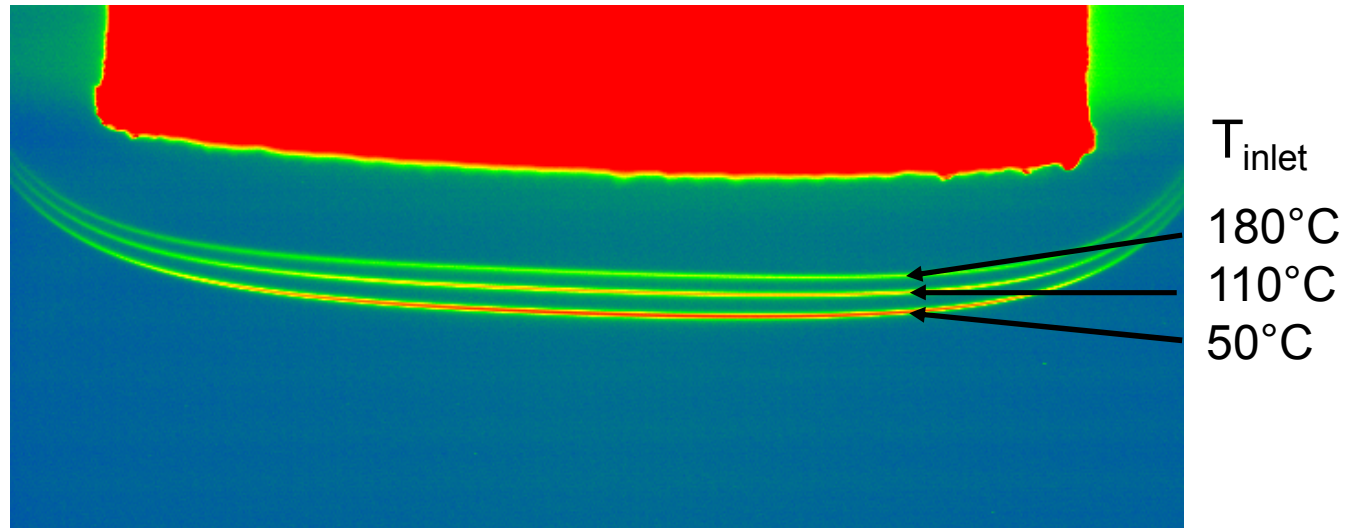
- Reduces buoyancy forces
 - *Smaller vertical temperature gradients*
- Increases the stable process window
 - Higher pressure / lower rotation rate capability
 - Improved hydride efficiency
- Reduced parasitic particulate formation (?)
 - Contrary to technical understanding
- More uniform wafer temperatures
 - Improved PL wavelength uniformity



Growth rates exhibit an unexpected dependence on inlet temperature



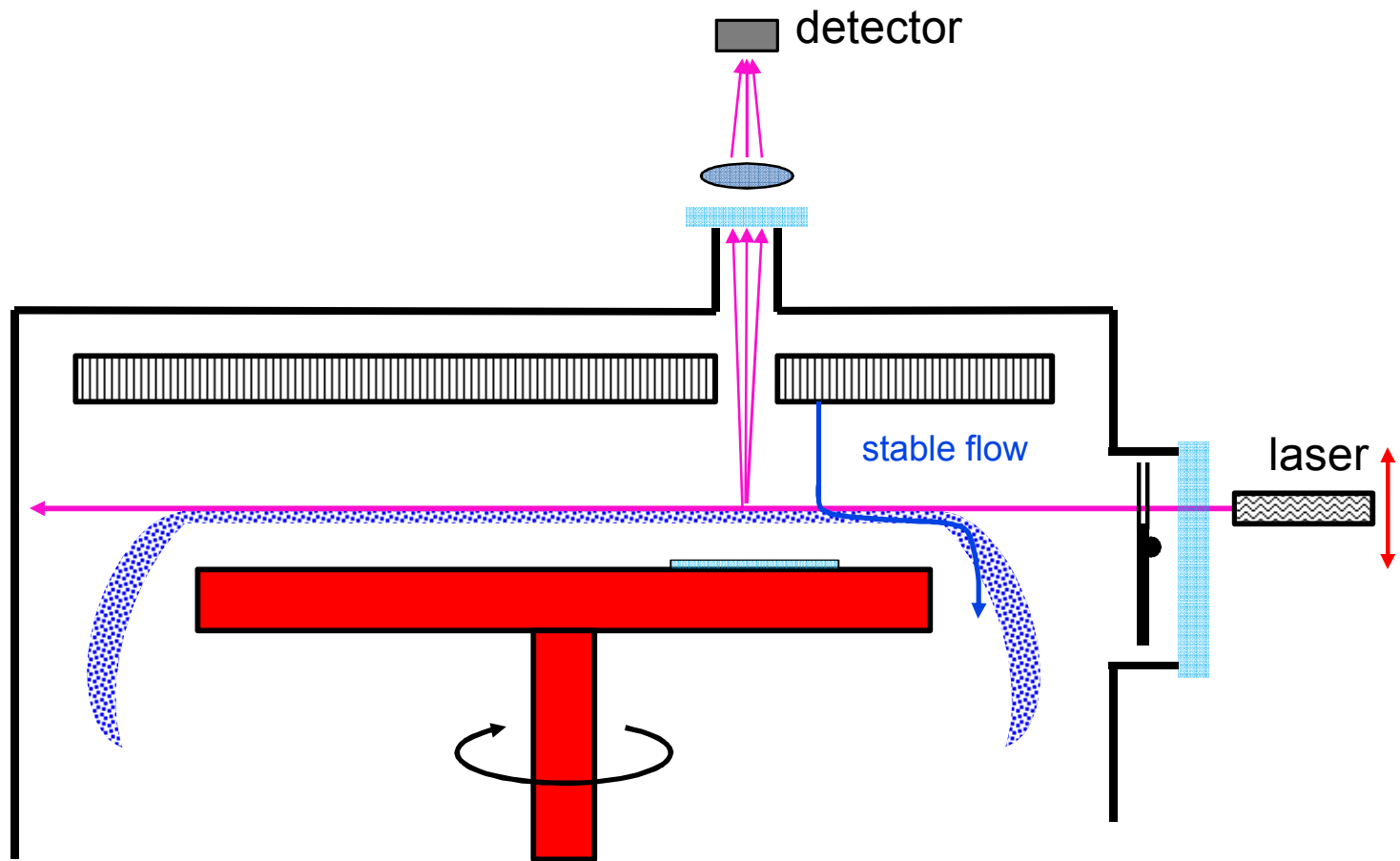
As inlet Temperature is raised, layer of particles gets closer to hot surface and scattering intensity drops



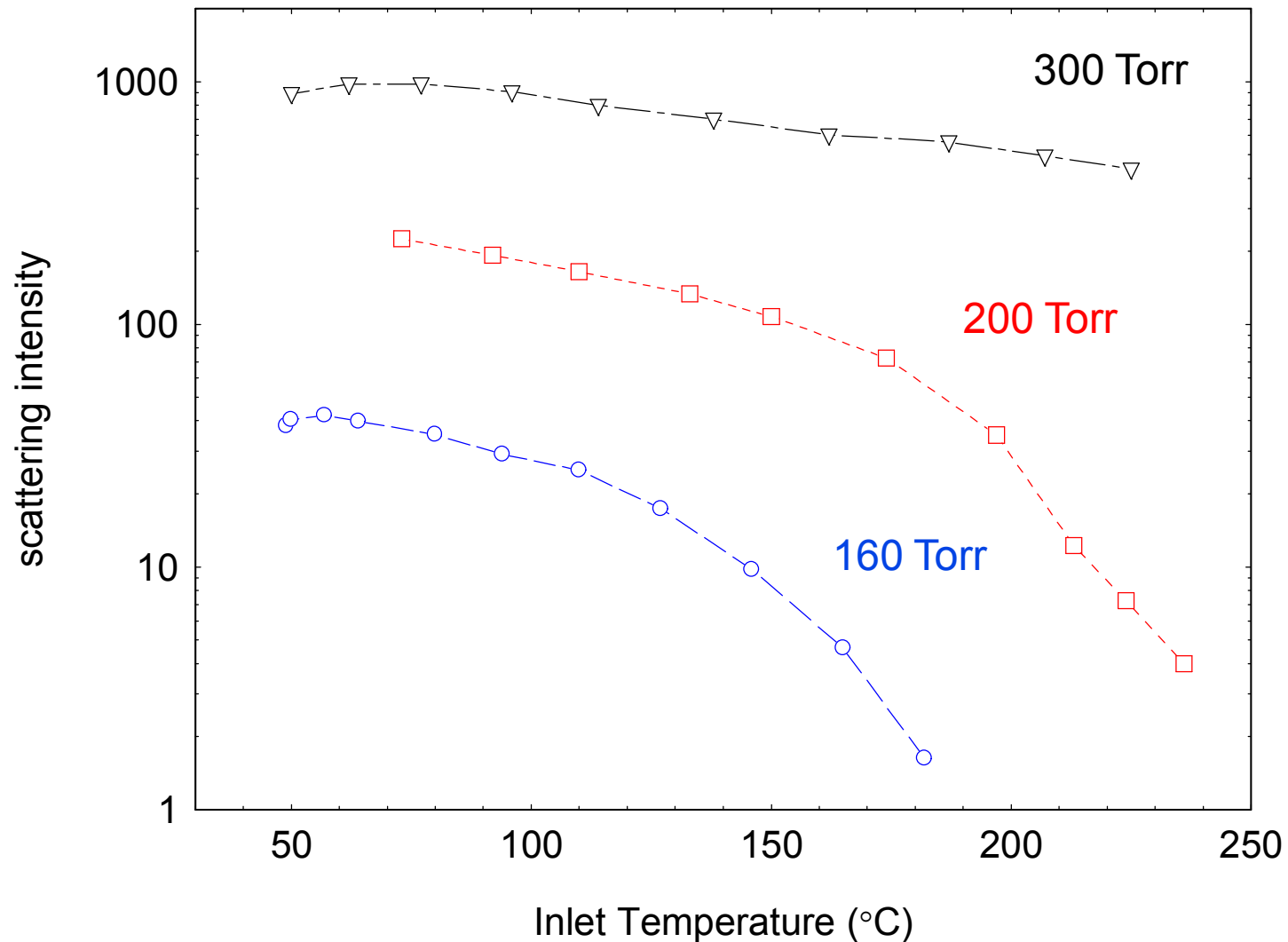
- 1) Shift in position towards hot surface expected from reduction in thermophoretic force
- 2) The intensity trend agrees qualitatively with Veeco MOCVD growth rate results

Fewer particles = higher growth rate

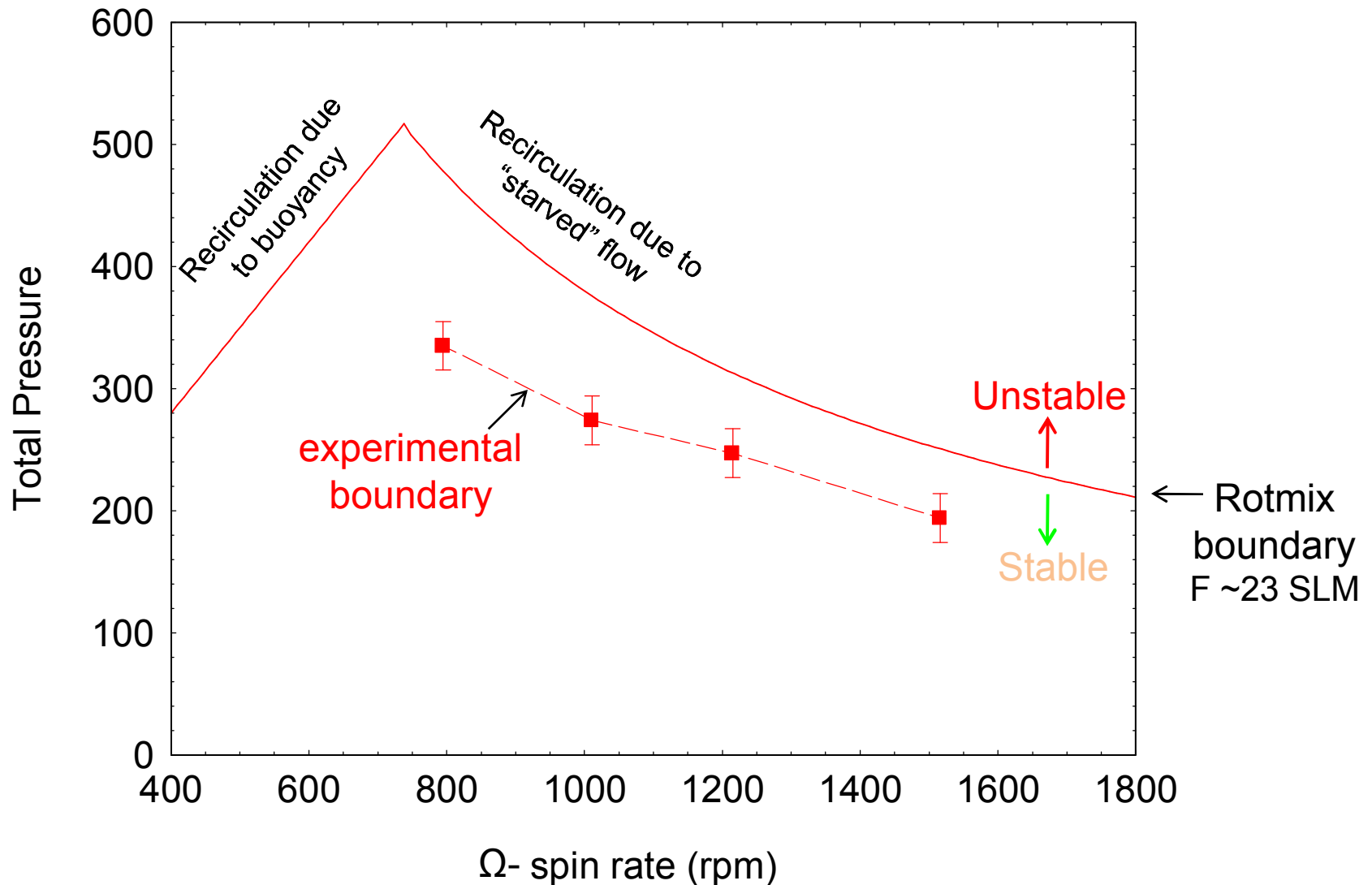
Schematic of light scattering in Veeco D-125 RDR at stable flow conditions



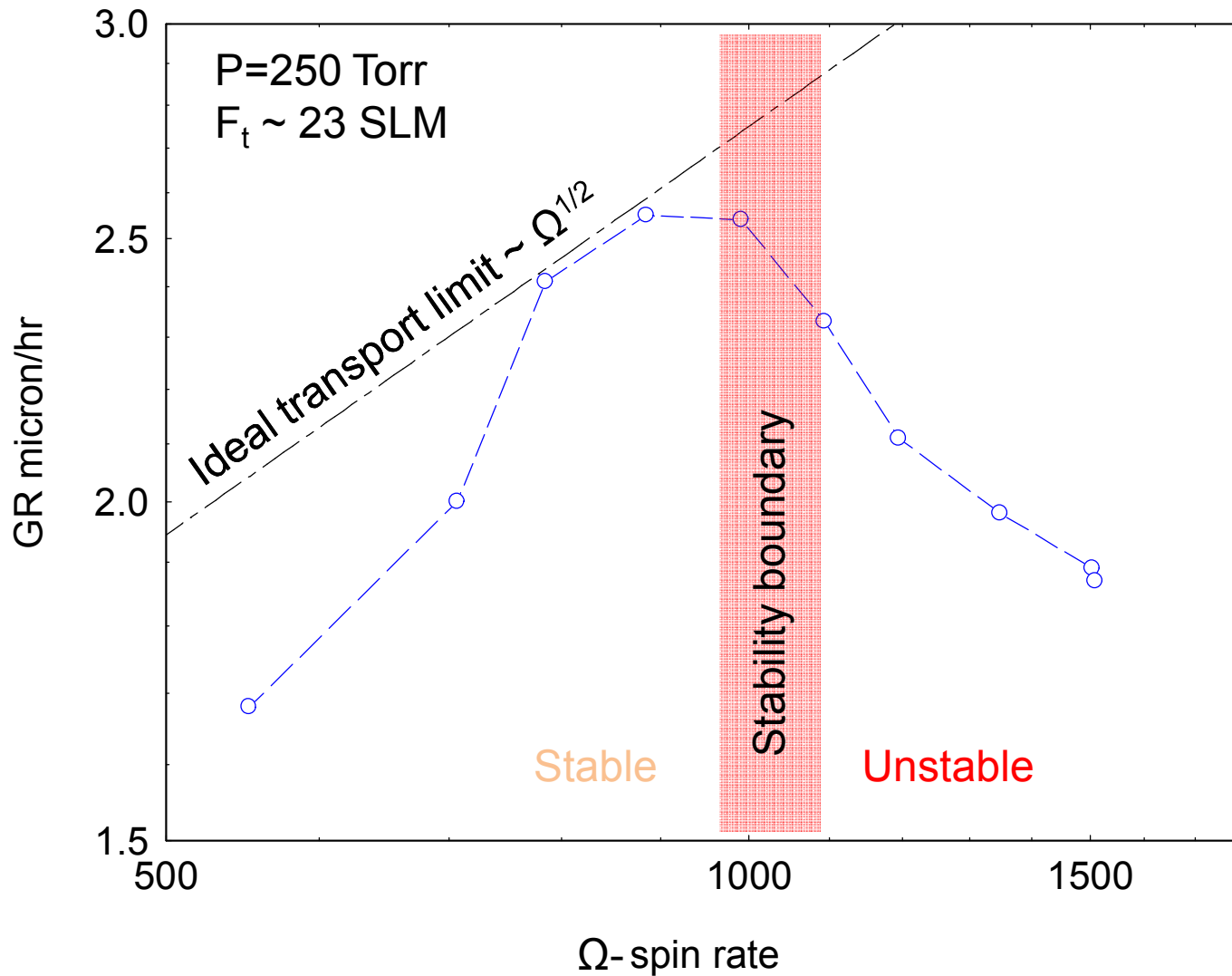
Depending on conditions, the response to a 200°C rise in inlet temperature can be modest ($\sim 3\times$) or significant ($>50\times$)



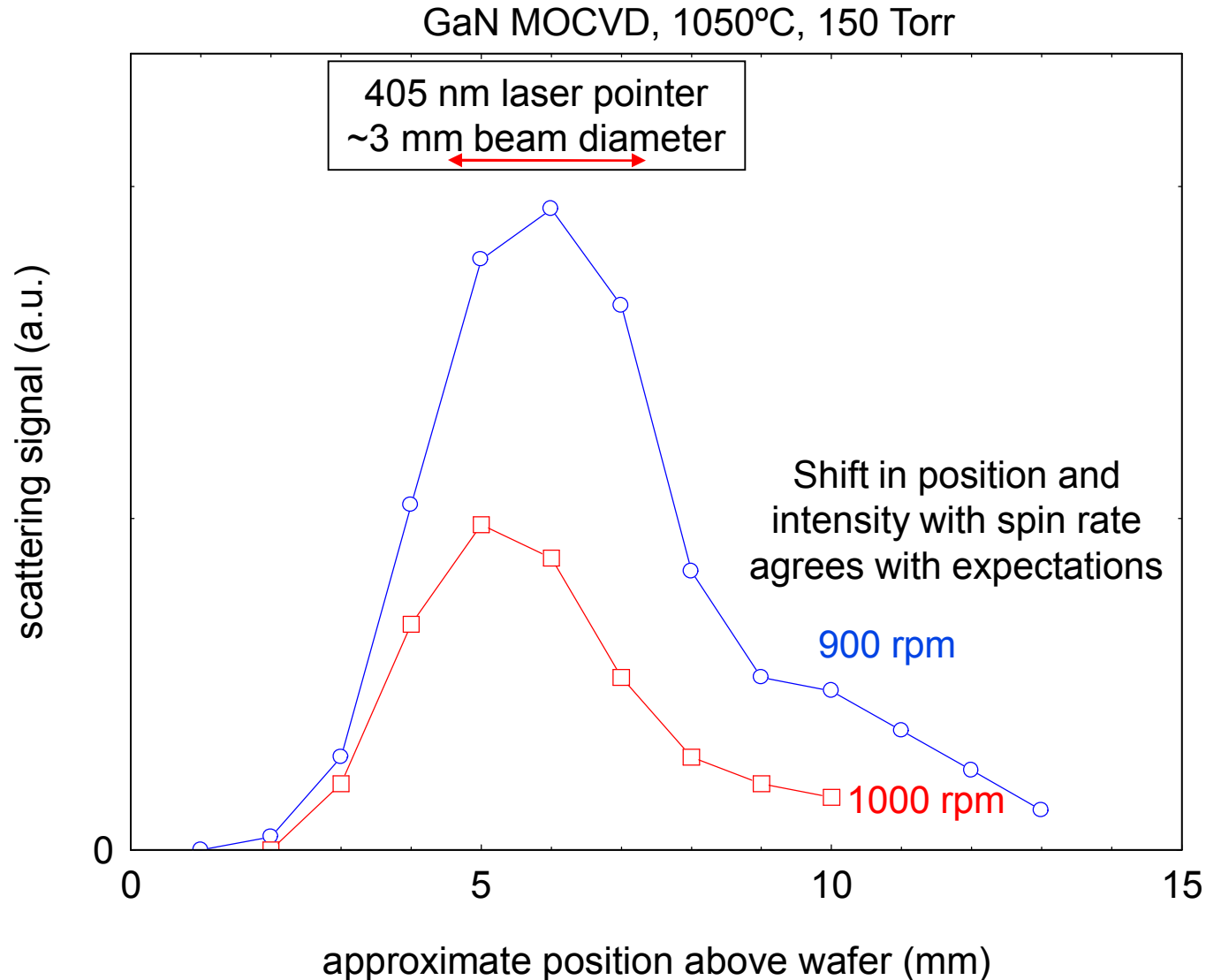
Experimental stability boundary exhibits approximate $\sim 1/\Omega$ dependence, but occurs at pressures somewhat lower than predicted



GaN MOCVD growth rate peaks near the stability boundary, drops rapidly at unstable conditions



“Proof-of-concept” results; light-scattering from particles under “stable” flow conditions

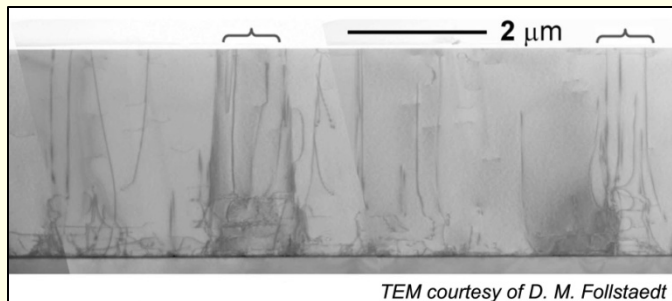




Topics for Discussion

- Current SSL programs at Sandia
- Heteroepitaxy studies – GaN on ...
- MOCVD reactor chemistry
- InGaN growth related to improving LED brightness
- Semipolar GaN growth – brighter green?

With high dislocation density, how can InGaN LEDs be so bright?

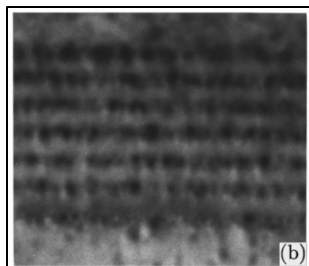


- High brightness LEDs are typically grown on high dislocation density GaN (10^9 cm^{-2}).
- With this large dislocation density LEDs in the other III-V materials would not work.

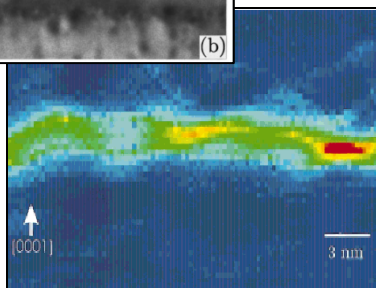
Are dislocations nonradiative recombination sites?

High efficiency suggests some type of carrier localization; the exact nature of which is unknown!

Narukawa, APL 70, 981 (1997)

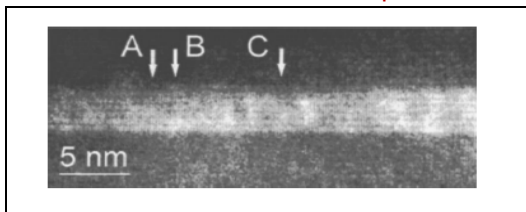


Quantum dot
formation or
compositional
modulation

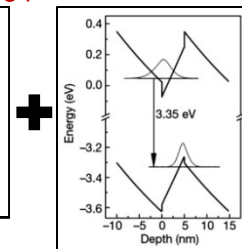


Gerthsen, Phys. Stat. A Sol. 177, 145 (2000).

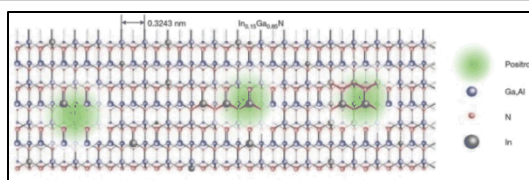
QW thickness fluctuations coupled to strong piezoelectric fields



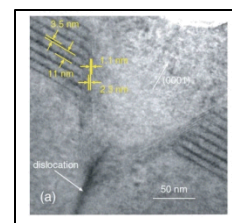
Graham, JAP 97, 103508 (2005)



Holes localized
at In-N valence
states, followed
by exciton
formation and
light emission.

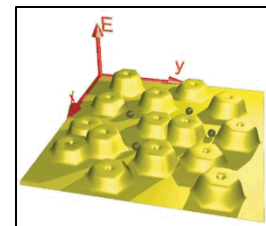


Chichibu, Nat. Mat. 5, 810 (2006)



Thinner
QWs
around
v-defects

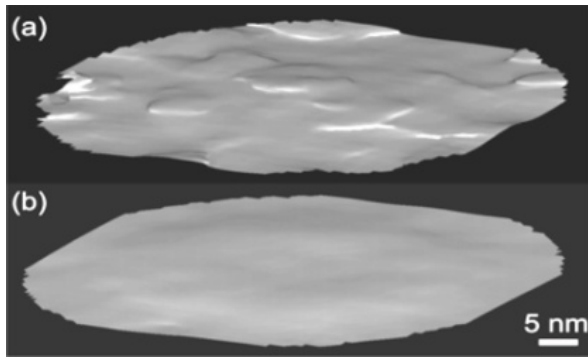
Energetic screening
around dislocations



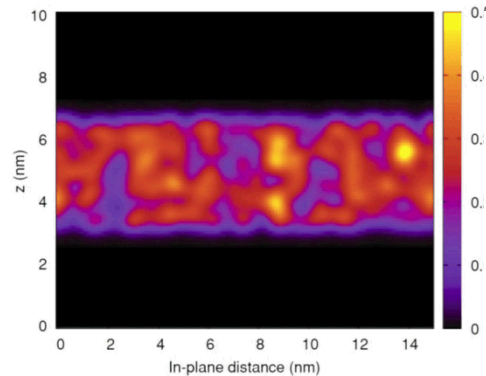
Hangleiter, PRL 95, 127402 (2005).

InGaN morphology may influence localization

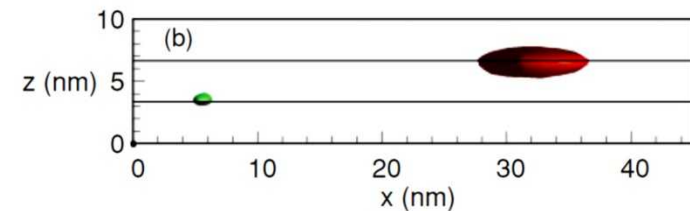
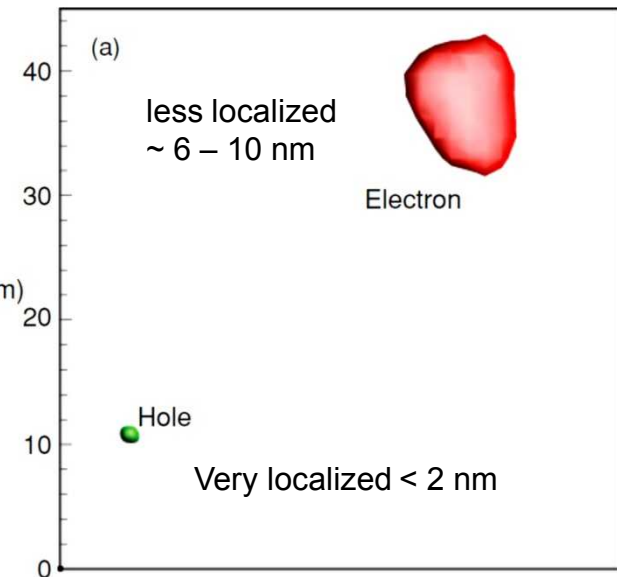
Watson-Parris, et al., *Phys. Rev B* 83, 115321 (2011)



An isoconcentration surface based on APT data illustrating the roughness of the lower and upper interface of an InGaN QW.



Indium fraction in a 3 nm thick QW with an average indium concentration of 25%.



The calculated ground state probability density of an electron (red) and a hole (green).

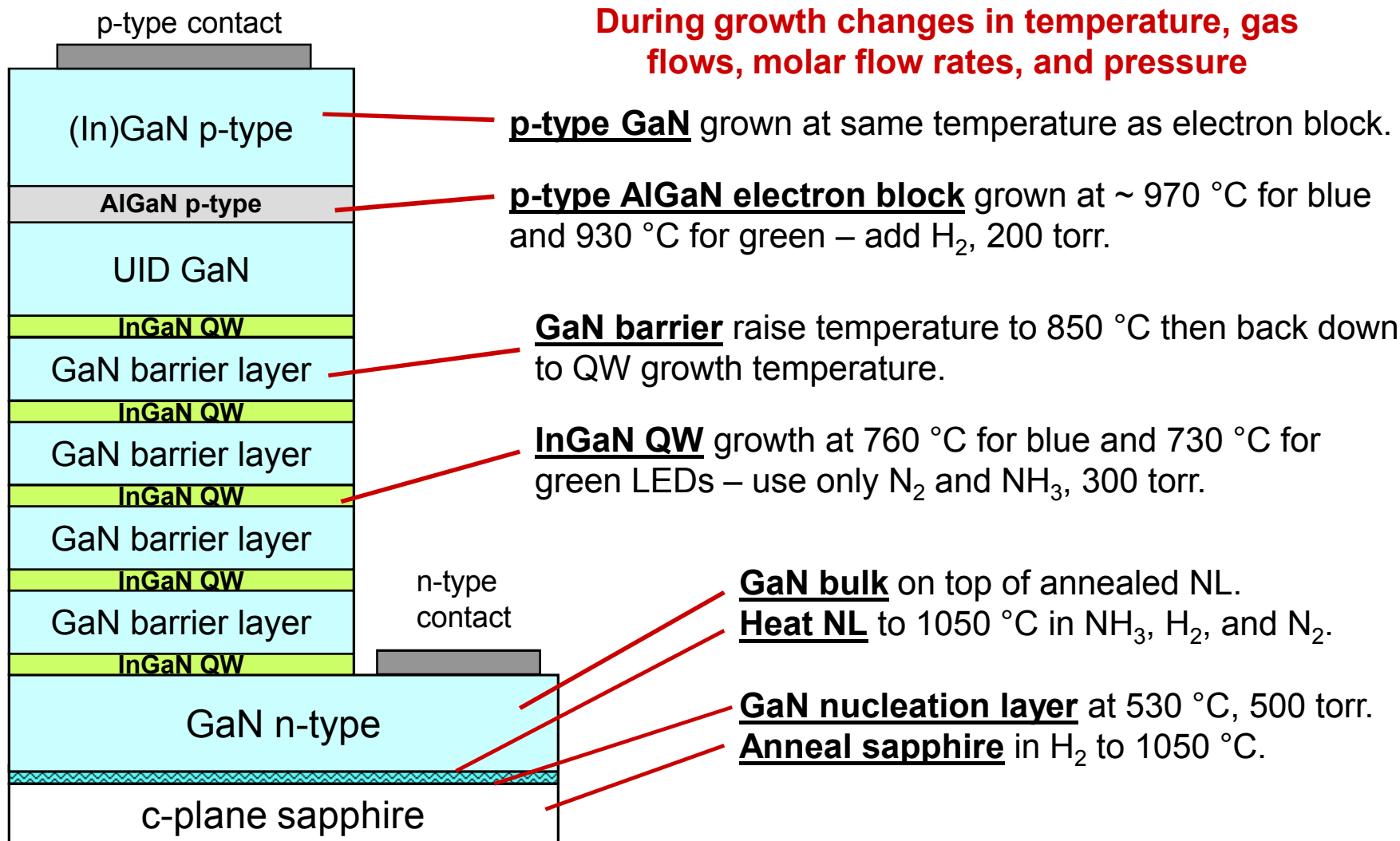
**Random fluctuations in alloy concentrations
sufficient to localize carriers.**

**Holes strongly localized in regions of higher
indium content.**

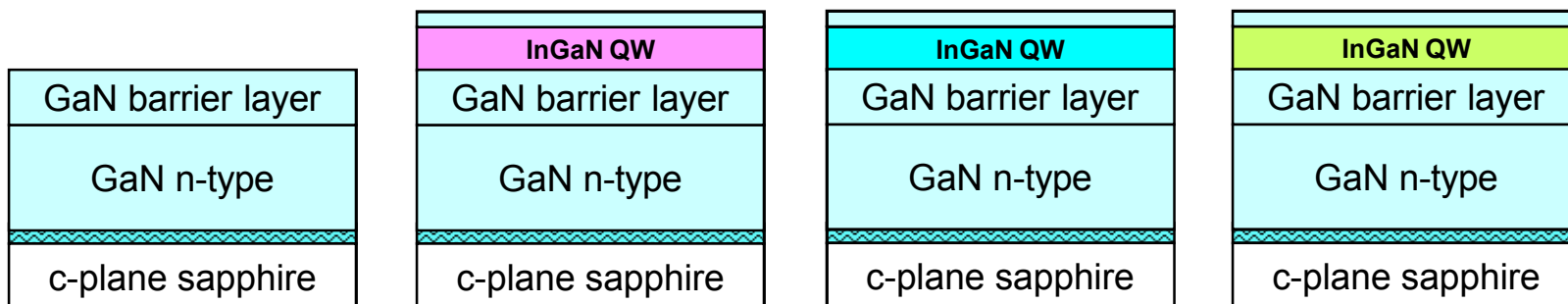
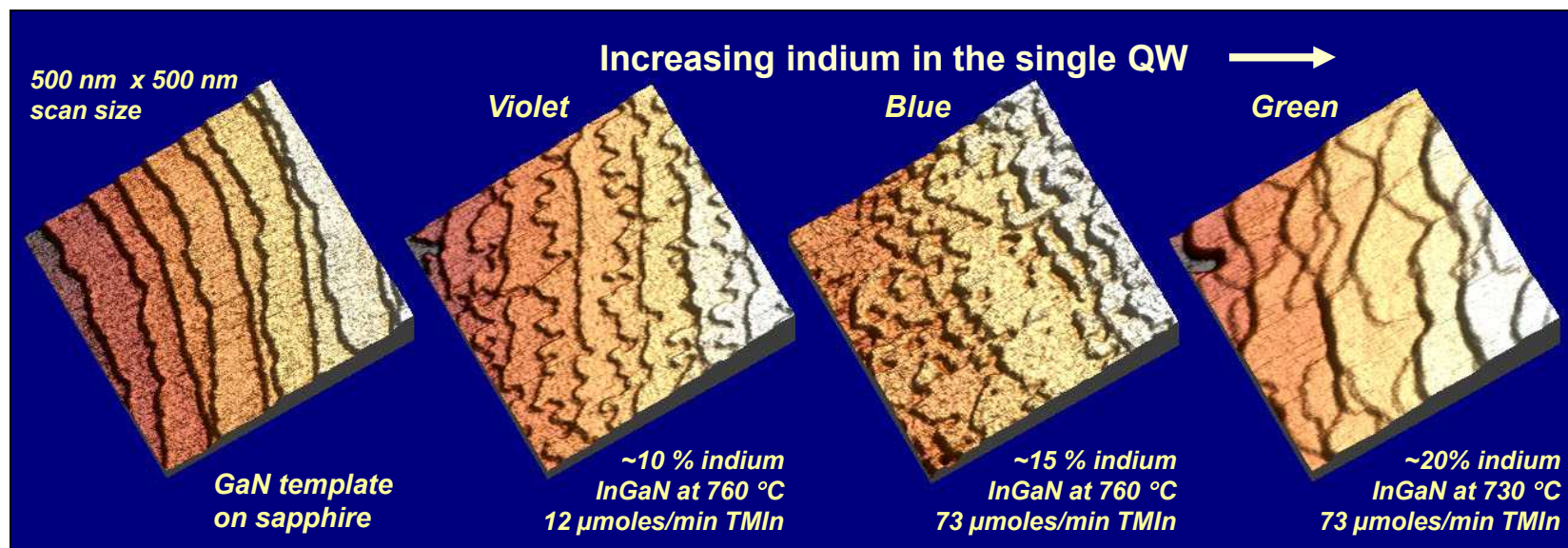
**Electrons are more strongly localized by mono-
layer well width fluctuations.**



Typical LED structure and growth procedure

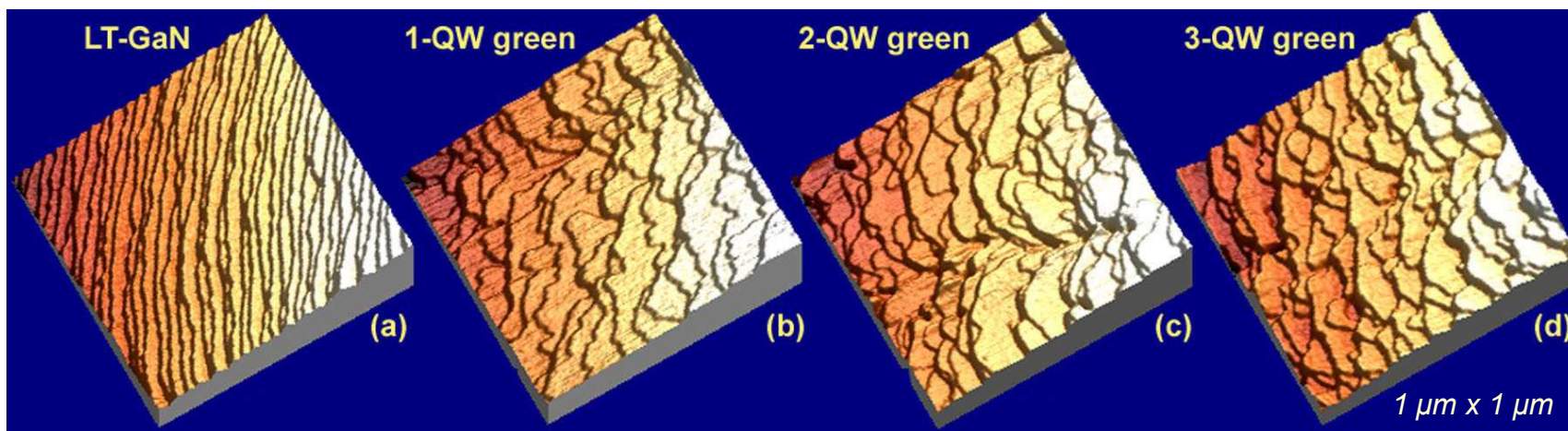


Increased indium in single QWs increases multi-layer steps

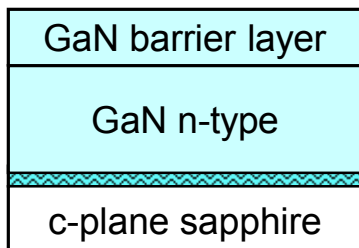


The multiple-layer step density increases as the indium incorporation increases

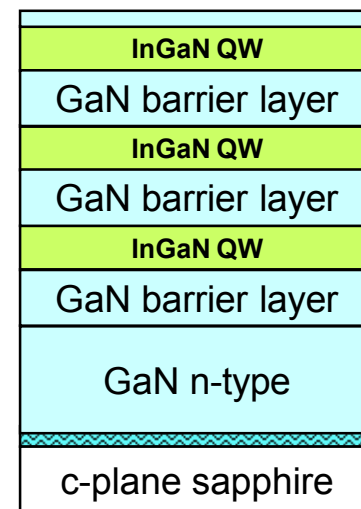
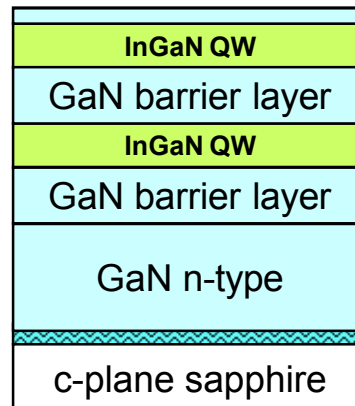
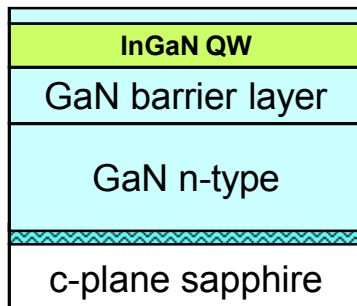
Observation of increased multi-layer steps in green MQWs



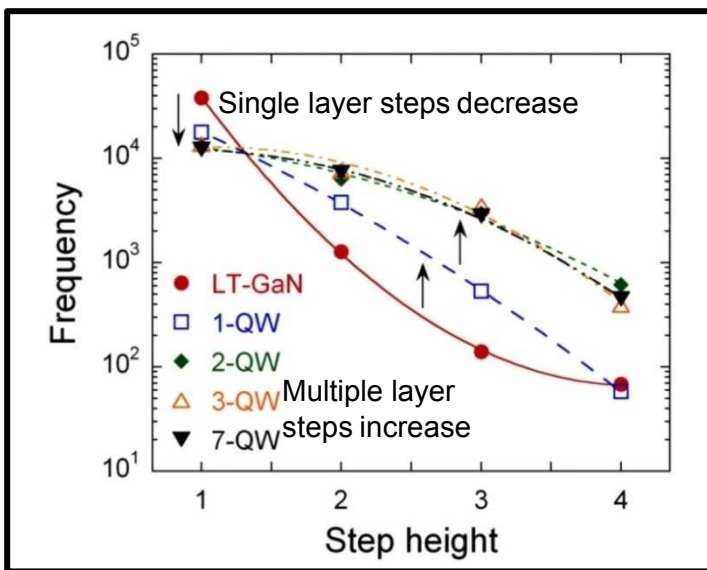
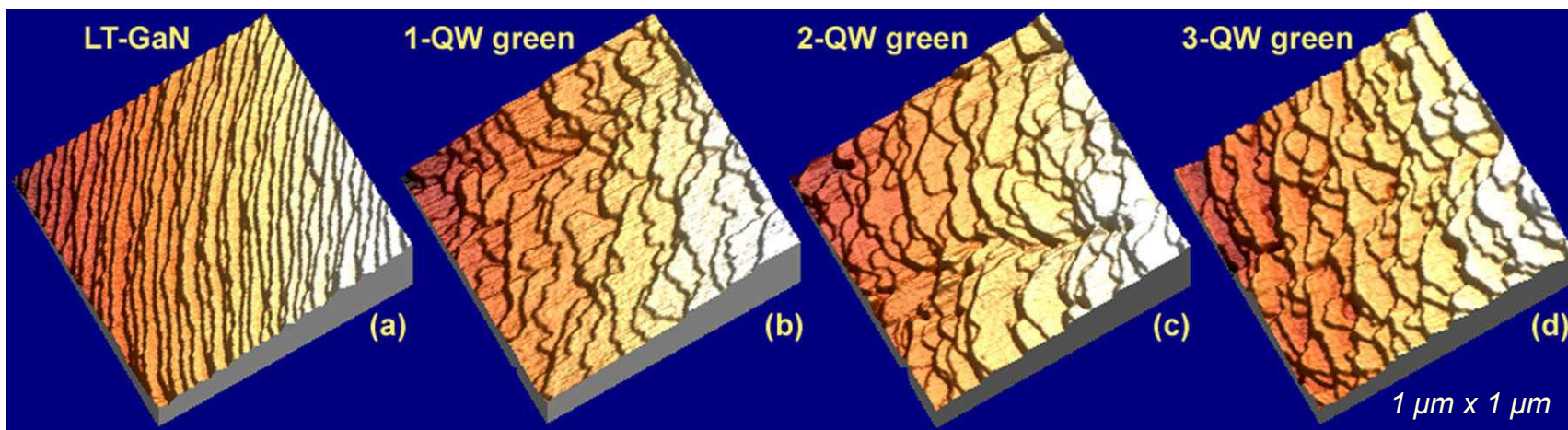
10 nm thick LT GaN barrier layer has the same step structure as the underlying HT GaN.



Addition of single 3 nm InGaN QW capped with 1.5 GaN barrier layer



Observation of increased multi-layer steps in green MQWs



As the number of QWs increases the number of multiple layer steps increases, but reaches a steady configuration after the 2nd QW.

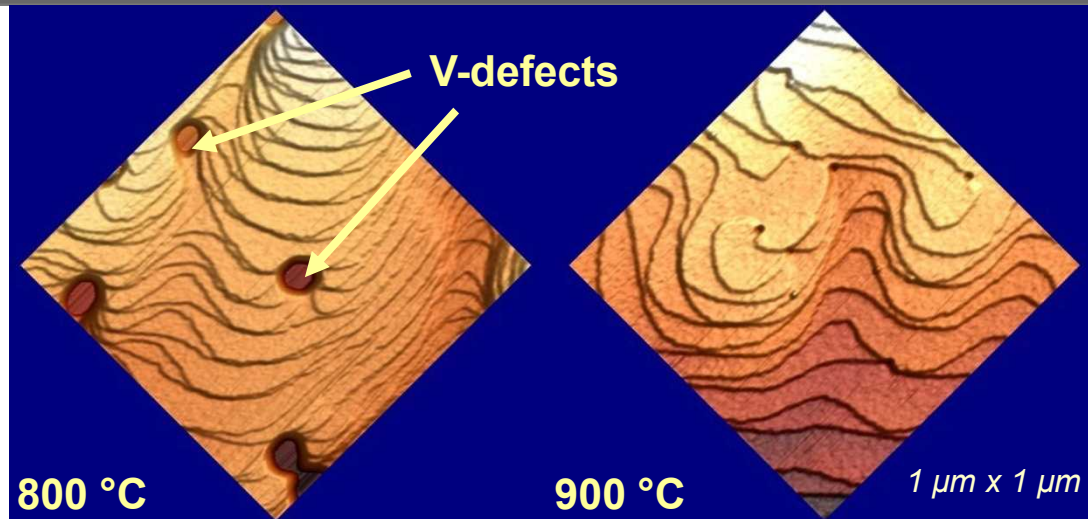
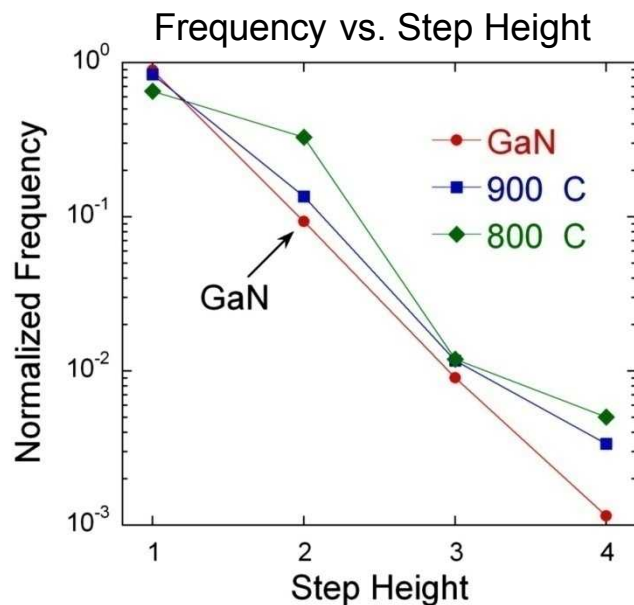
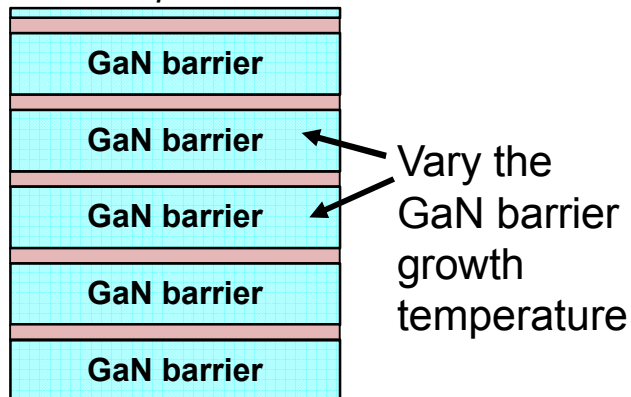
Suggests that while the InGa_N QWs roughen the surface, the Ga_N barrier layer smooths the surface.

What are the smoothing mechanisms?

GaN barrier growth temperature can be used to control step morphology

Vary the GaN barrier temperature, keep green QW growth conditions the same.

MQW sample structure

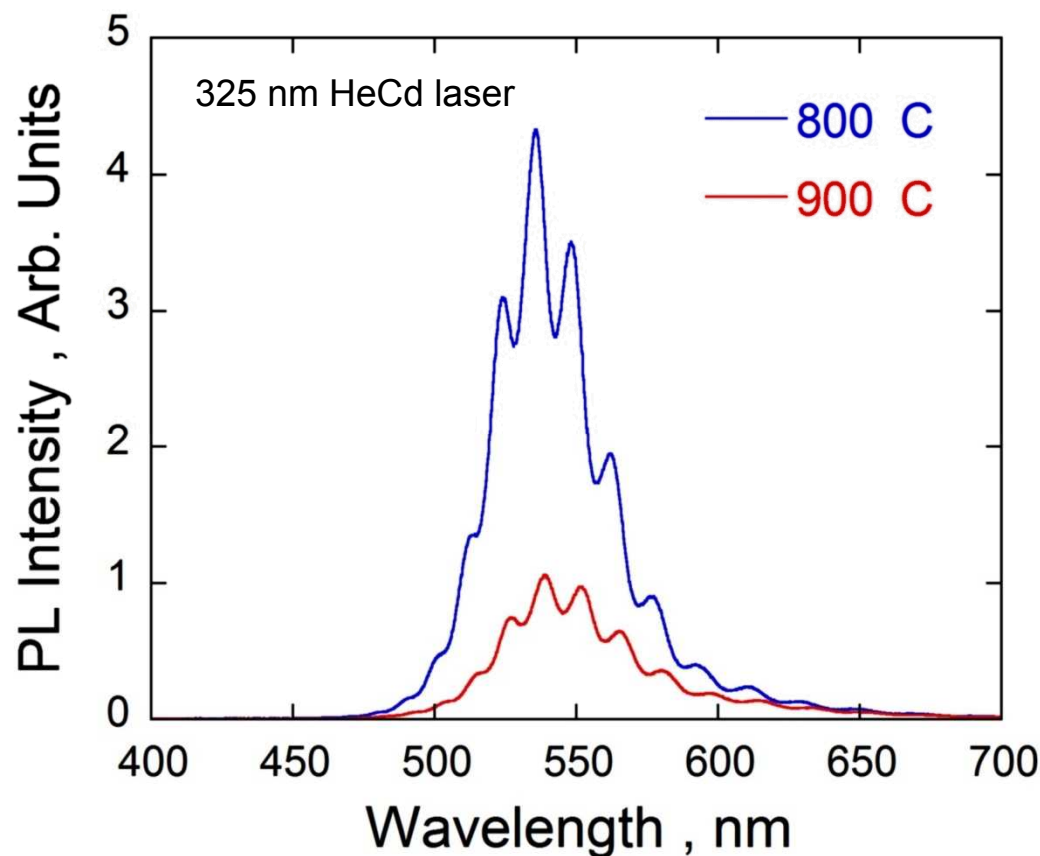


Increased number of double layer steps at 800 °C compared to 900 °C.

The 900 °C step height frequency distribution is closer to the starting GaN template than 800 °C. Implies - higher temperature GaN growth can be used to control the step height frequency and increase the surface smoothness.

PL analysis of the green MQWs with different GaN barrier growth temperature

Higher PL intensity for GaN barriers at 800 °C



Same intensity and wavelength trends are observed for resonant optical pumping at 407 nm.

Suggests that the rougher step morphology produces QW with increased PL intensity.

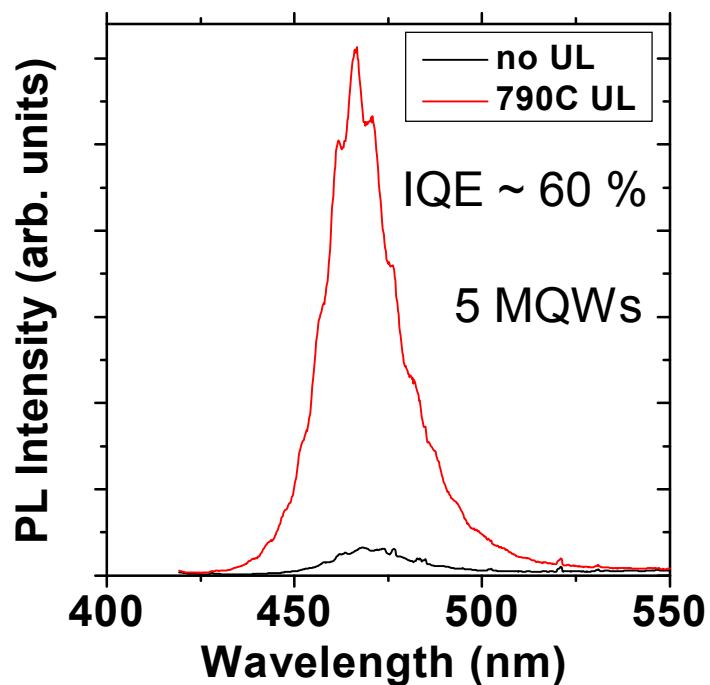
The morphology could produce QW thickness fluctuations coupled to the strong piezo-electric fields to produce electron/hole localization. Graham et al., JAP 97, 103508 (2005).

InGaN underlayers increase IQE of MQWs

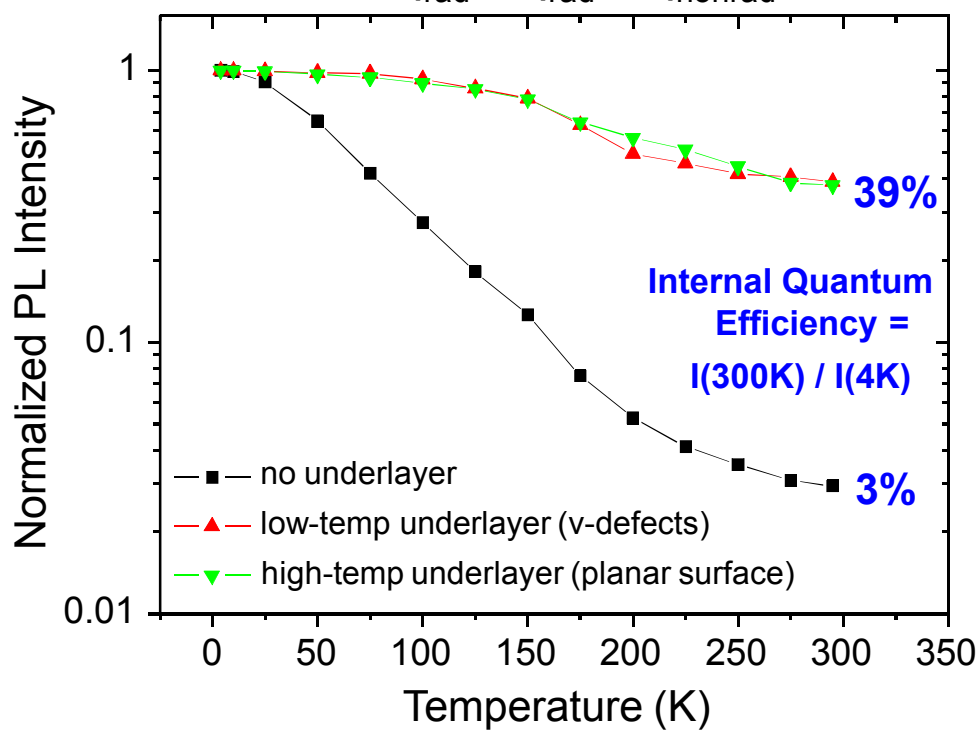
Especially help emission of single QWs

Temperature dependent PL studies by Mary Crawford

15X increase in integrated PL emission with InGaN UL



$$\text{IQE} = \eta_{\text{rad}} / (\eta_{\text{rad}} + \eta_{\text{nonrad}})$$



Underlayers enhance efficiency compared to same MQW with no underlayer.

Optimal MQW growth conditions

- InGaN underlayers
 - 2-3% indium, 850- 880 °C, ~ 200 nm thick
- InGaN QWs growth
 - High temperature – high indium flow
 - indium incorporation limited by indium desorption
- Vary GaN barrier growth temperature
 - Least influence on 440 nm, most influence on 530 nm

Have achieved IQE of 60 % for 440 nm MQWs



Topics for Discussion

- Current SSL programs at Sandia
- Heteroepitaxy studies – GaN on sapphire
- MOCVD reactor chemistry
- InGaN growth related to improving LED brightness
- Semipolar GaN growth – brighter green?

Semi-polar GaN Materials Technology for High IQE Green LEDs

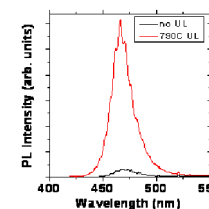
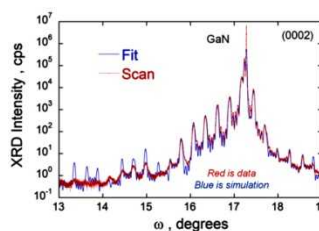
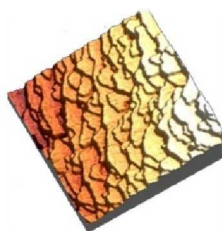
Overall Goal: Fabricate a 540 nm LED with an IQE of 50%.

The proposed work relates to subtask A.1.2 of MYPP(Emitter materials research) which encourages the development of highly-efficient green and red emitters to greatly improve the efficiency of color-mixing LED packages.

Metric(s)	2009 Status(s)	2020 Target(s)
Internal Quantum Efficiency (IQE) @ 35 A/cm ²	80% (Blue) 40% (Green) ← Focus 75% (Red) ←	90% (Blue, Green, Red)
External Quantum Efficiency (EQE) @ 35 A/cm ²	64% (Blue) 30% (Green) 38% (Red)	81% (Blue, Green, Red)

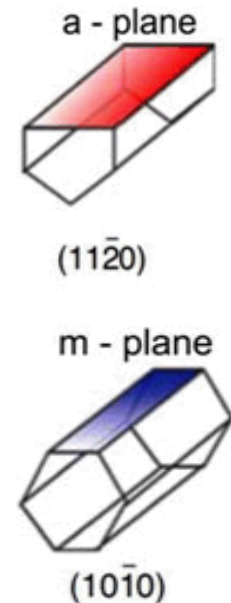
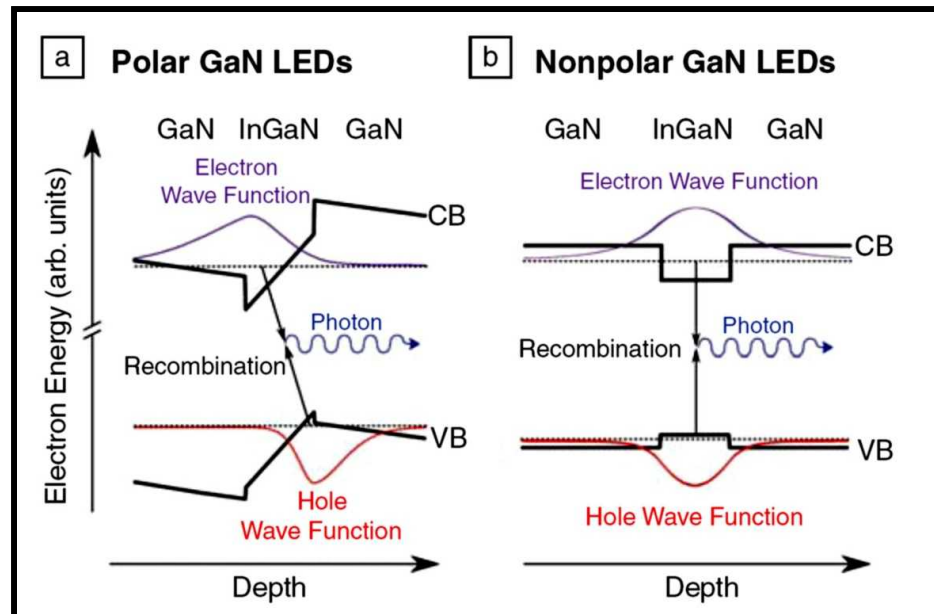
Process: Explore m-plane and semipolar GaN orientations to determine which orientations produce the highest indium incorporation (longest wavelength) and highest IQE.

substrates from



Why nonpolar or semipolar GaN?

From Speck and Chichibu, MRS BULLETIN 34, 304, (2009)



For Polar

- Electron and hole wavefunction spatial separation reduces likelihood of radiative recombination. Nonpolar – no spatial separation – better wavefunction overlap.
- The carrier confinement and the electron and hole wavefunction separation can be balanced if QW is ~ 25 Å – high carrier density. Nonpolar – can make the QWs thicker - lower carrier density.
- EL blue shift due to energy tail states caused by thickness fluctuations in the QWs grown at low temperature – efficiency droop? Nonpolar – might still have these thickness fluctuations.

No QCSE on nonpolar so need to incorporate more indium achieve similar wavelengths

Possibly higher indium incorporation on semipolar GaN

On c-plane GaN, indium is limited to ~ 22%.

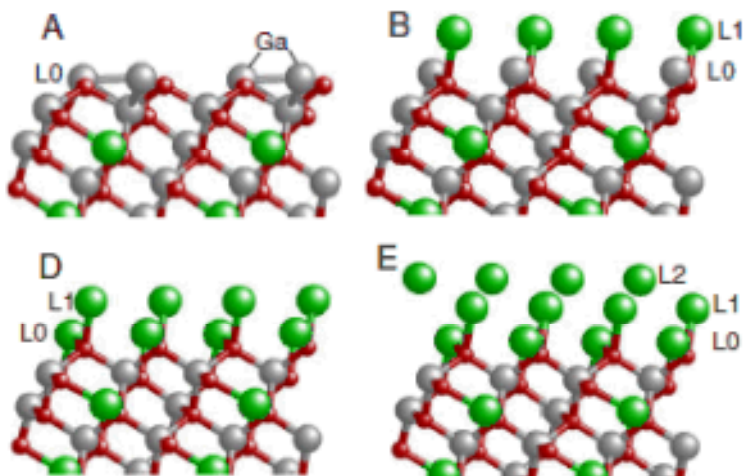


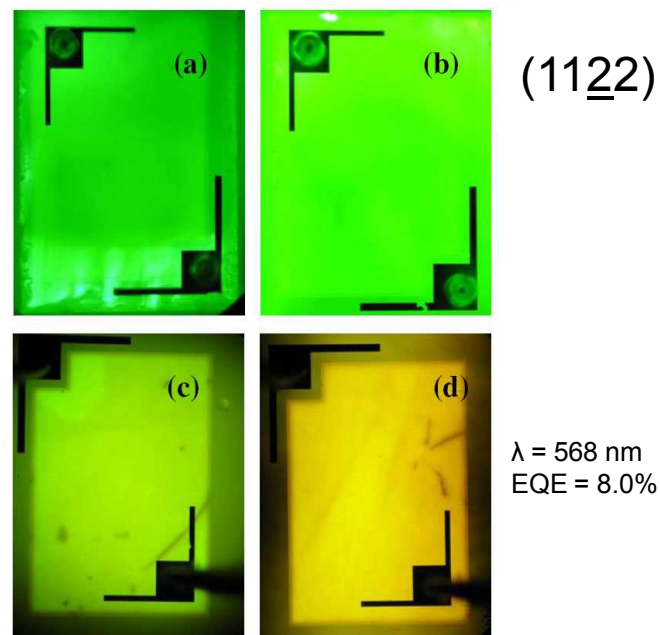
FIG. 3. (Color online) InGaN(11 $\bar{2}2$) surfaces. A, B, D, and E contain successively more In atoms in layers L0, L1, and L2. Indium atoms are large green spheres, Ga atoms are gray, and N atoms are small red spheres.

J. E. Northrup, Appl. Phys. Lett. 95, 133107 (2009).

Recent DFT calculations predict greater indium incorporation on GaN (11-22) compared to GaN (10-11) due to reduced strain between the surface incorporated indium atoms.

Implies that higher indium concentrations > 22% can be achieved leading to yellow and longer wavelength LEDs.

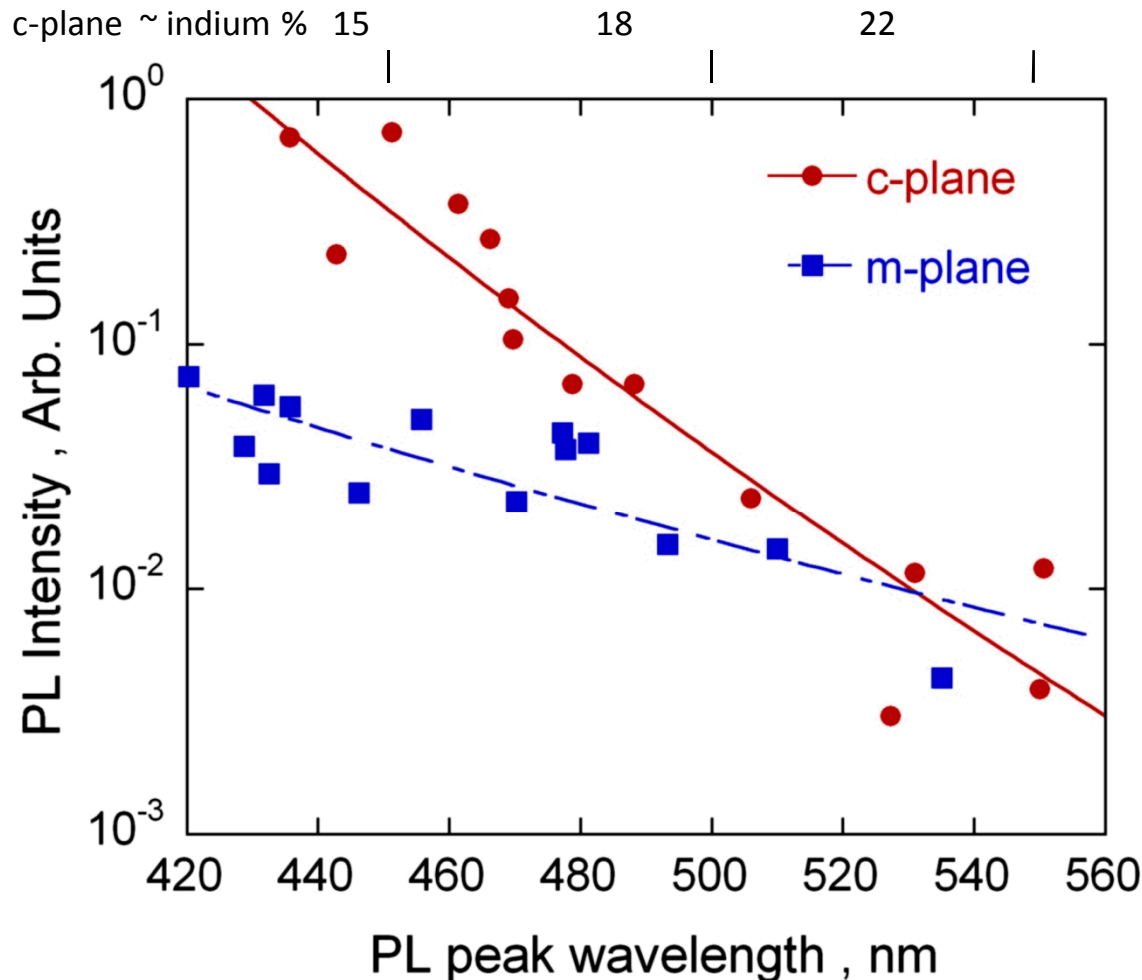
Fellows et al., JJAP 47, 7854 (2008).



LEDs shown at 1 mA forward bias

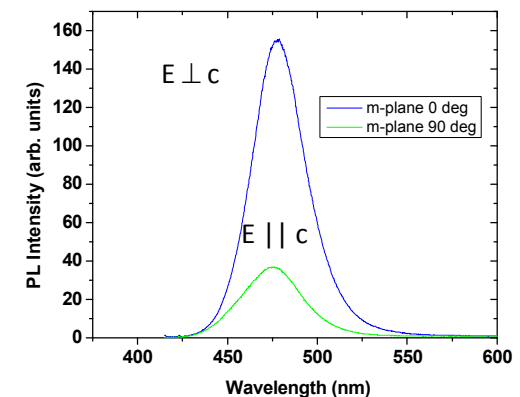
Since there is minimal QCSE, there has to be ~ 40% indium concentration in the QW to reach these wavelengths.

Comparison of MQWs on c- and m-plane GaN



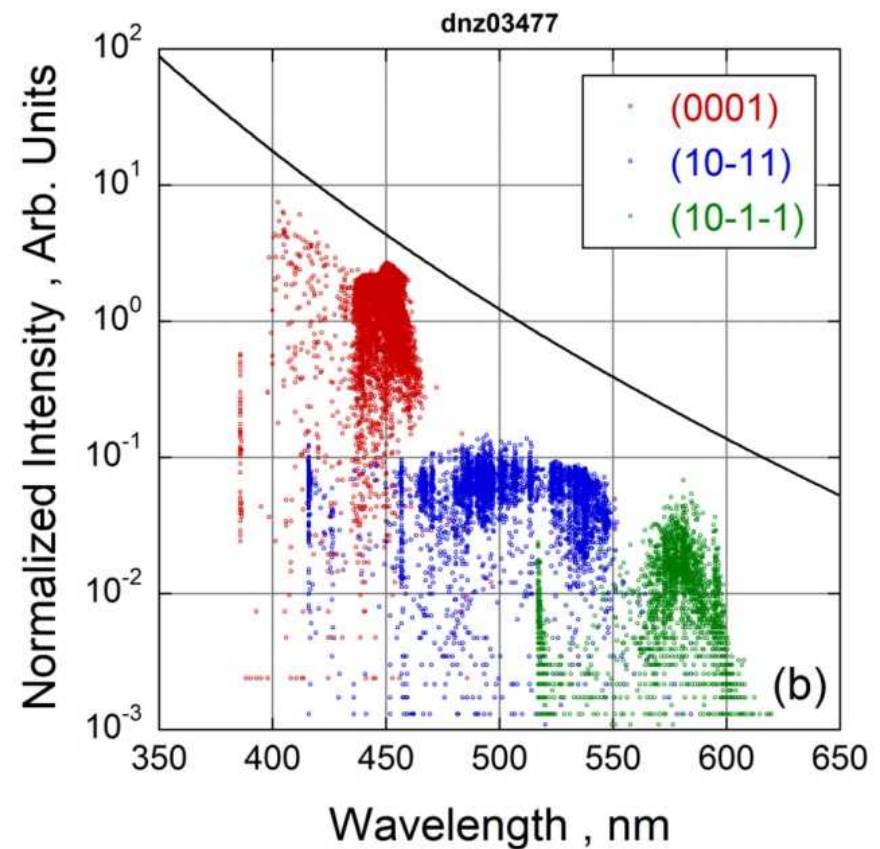
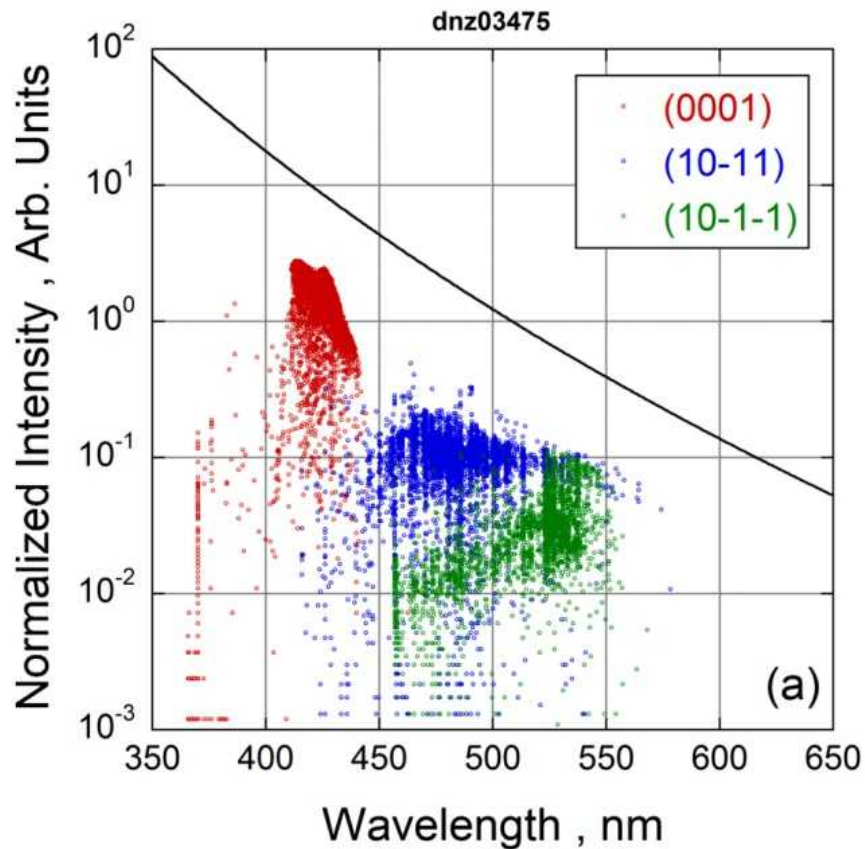
- The PL intensity of MQWs on c-plane decreases more as the wavelength increases compared to m-plane.
- Polarization dependence of the m-plane MQWs not accounted for in these plots.
- Indicates that for $\lambda > 530$ nm MQW on m-plane might be brighter than on c-plane.

Polarization-dependent PL of m-plane MQWs



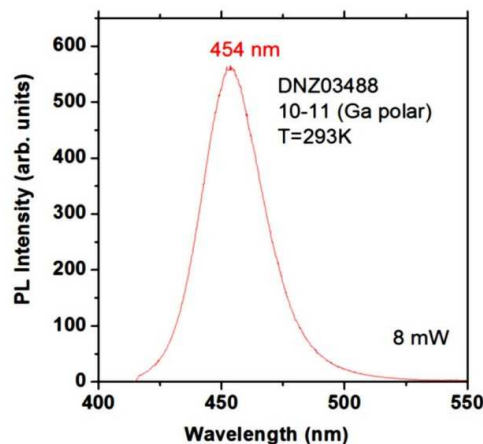
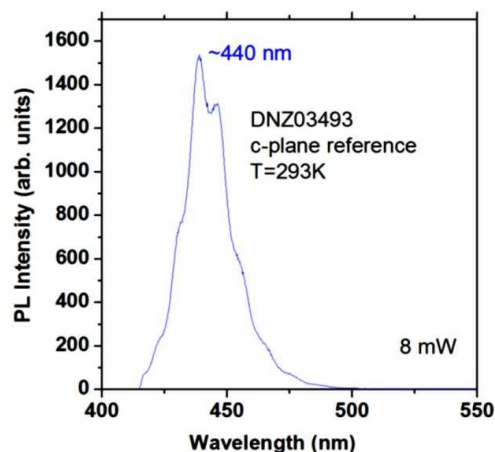
Longer wavelength emission on semipolar substrates

Co-load c-plane and Ga-polar (10-11) and N-polar (10-1-1) substrates – grow same MQW sample on all three substrates.



Observe that PL wavelengths are longest on (10-1-1), followed by (10-11) and c-plane

Recent IQE of MQWs on c-plane and (10-11)



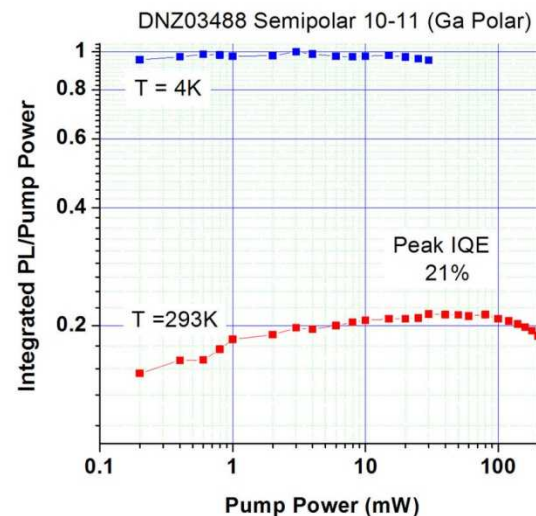
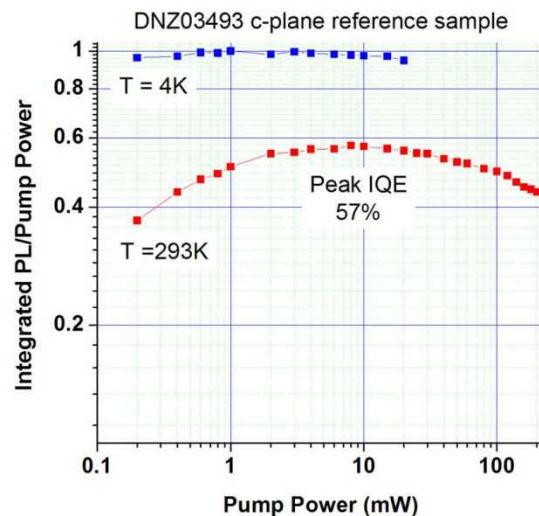
Define IQE as PL (300K)/PL(4K)

Perform PL at various pump powers to identify:

- Max PL intensity/pump power at 4K (100% IQE)
- **Peak IQE** at room temperature

Result: Peak IQE ~ 21% at room temperature. Also achieved ~ 11% for MQWs on m-plane GaN

Outstanding issue: IQE shows little variation with pump power—need to understand



Thanks to:

Sandia Colleagues:

Randy Creighton – growth chemistry experiments.
Steve R. Lee – XRD analysis, strain relaxed InGaN
Mary H. Crawford – PL, LED studies
Mike Coltrin – growth modeling.
Andy Armstrong – DLOS spectroscopy of defects.
Andy Allerman – AlGaN MOCVD

Karen Cross – AFM images.
J. J. Figiel – MOCVD tech.
J. M. Kempisty – MOCVD tech.
R. M. Biefeld – Manager